ASM Pacific Technology

2020
Annual Results Presentation

26 February 2021

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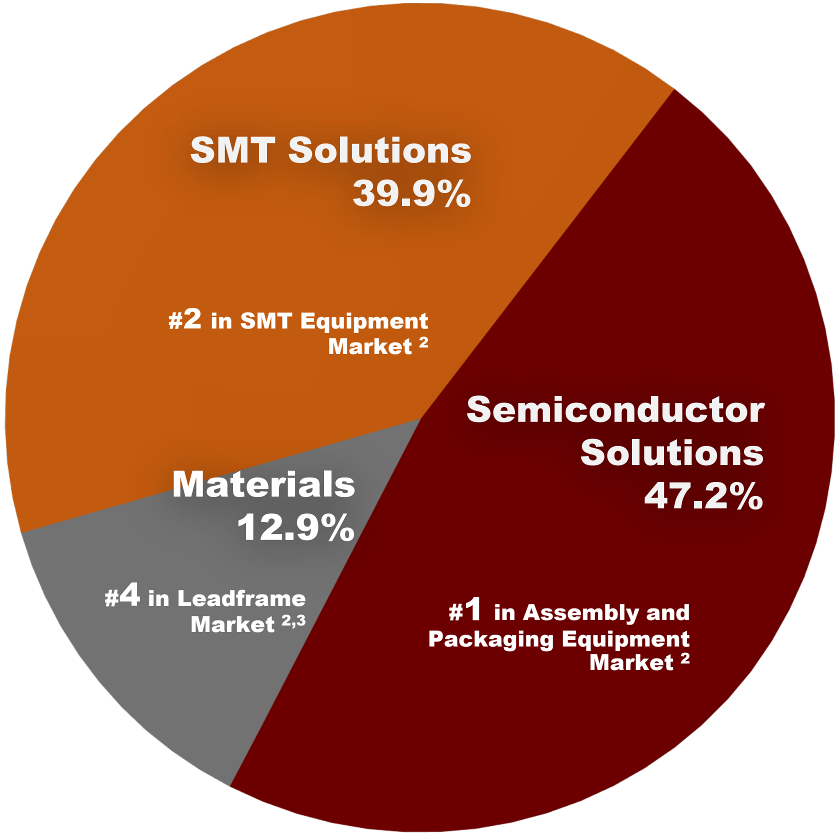
Company Overview

Company Overview

2020 Segment Revenue Contribution

We are a leading global supplier of hardware and software solutions for the manufacture of semiconductors and electronics



1975	1989	USD 6.2bn	Top 100 Global Technology Leaders
Incorporated	Listed in Hong Kong Stock Exchange	Market Capitalisation[1]	Recognised by Thomson Reuters (2018)

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[1] As of 19 February 2021

[2] VLSI, SMT and SEMI, Management Estimates

[3] Materials Segment will be de-consolidated and equity accounted for from 29 December 2020

Geographical
Presence

● **Sales Offices**

⬢ **Business Centre / R&D / Manufacturing Site**

>2,000

Global R&D staff

>1,500

Patents on leading edge technologies

11

R&D centres worldwide

12

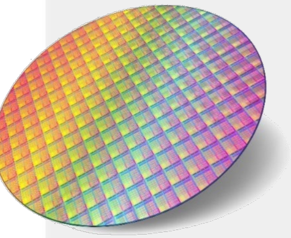
Manufacturing facilities

Our Core Capabilities

Comprehensive Suite of Packaging & Assembly and SMT Solutions for Multiple End Applications

(A General Process Flow for IC and Discrete)

From Wafer…



Deposition and Plating

Wafer Backside Grinding

Wafer Mount & Singulation

Grooving

Saw **or Laser**

Die Bonding and Epoxy Curing

Plasma and **Wire Bonding**

Automated Optical Inspection

Molding & PMC

Marking

BGA, QFN and LGA Packages

Solder Ball Placement

Singulation

Leaded Package

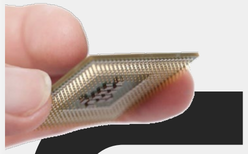
Plating

Trim & Form

Testing & Packing

Test Handling

Tester



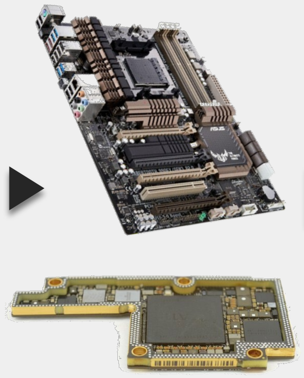
1st Level Packaging (SEMI Solutions)

Solder Paste Printing

Solder Paste Measurement

Component Placement

Post Placement



To End Device

2nd Level Packaging (SMT Solutions)

Legend

Solution offered by ASMPT

2020 Financial and Operational Highlights

2020 Group Highlights

	FY20		Q4 20		
		YoY*		QoQ	YoY*
Bookings (USD)	2,382m	+16.7%	658m	+12.9%	+46.3%
Revenue (USD)	2,177m	+6.3%	634m	+15.2%	+10.5%
Gross Margin[1]	33.6%	-114 bps	33.0%	+6 bps	-179 bps
Net Profit Margin[1]	5.9%	+202 bps	7.7%	+220 bps	+269 bps

Key Highlights for FY2020:

- Record 4th Quarter bookings, reversing seasonally low Q4 trend
- Automotive & Industrial bookings bottomed out end-1H20
- Broadened customer demand for AP tools
- Group's AP (both SEMI & SMT) FY20 Revenue contribution ▲ >50% YoY

Main Drivers for FY2020:

- Accelerated digital transformation trends drove:
  - Equipment capacity expansion
  - Advanced Packaging (AP) solutions
- 5G roll-out
- General automotive recovery and automotive electrification

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[1] Excluding one-off items and related tax impact

*Period to period variances calculated using HKD

2020 Group Highlights – Continued

Group (excluding one-off items and related tax impact)	FY20		Q4 20		
		YoY		QoQ	YoY
Gross Margin	33.6%	-114 bps	33.0%	+6 bps	-179 bps
Net Profit (HKD)	1,002m	+61.1%	378m	+61.5%	+70.2%
Net Profit Margin	5.9%	+202 bps	7.7%	+220 bps	+269 bps

Group (including one-off items and related tax impact)	FY20		Q4 20		
		YoY		QoQ	YoY
Gross Margin	32.5%	-232 bps	28.9%	-399 bps	-584 bps
Net Profit (HKD)	1,631m	+162.0%	1,006m	+330.0%	+353.4%
Net Profit Margin	9.7%	+574 bps	20.5%	+1,497 bps	+1,547 bps

One-off Items for FY2020:

- Gain of HK$859m from planned 55.56% divestment of Materials Segment
- Strategic initiative-related provisions of HK$255m

2020 Semiconductor Solutions Segment Highlights

	FY20		Q4 20		
		YoY*		QoQ	YoY*
Bookings (USD)	**1,158m**	**+25.9%**	**334m**	**+16.0%**	**+84.9%**
Revenue (USD)	**1,027m**	**+13.8%**	**307m**	**+24.1%**	**+17.3%**
Gross Margin[1]	**40.7%**	**-43 bps**	**39.0%**	**-95 bps**	**-180 bps**

Key Highlights for Q4 2020:

- Record 4th Quarter Bookings and Revenue
- IC/Discrete
  - Personal computing devices, HPC, Automotive & Power management
  - China: 5G infrastructure, Capacity ramp-up
- Optoelectronics
  - General lighting / conventional display applications
  - Extensive customer engagements on mini and micro LED
- CIS Q4 Revenue ▼ YoY, ▲ QoQ
- Mainstream Die / Wire Bonders: Very strong Q4 Revenue YoY Growth
- FY20 GM ▼ slightly due to product mix

[1] Excluding one-off items

***Period to period variances calculated using HKD**

2020 SMT Solutions Highlights

	FY20		Q4 20		
		YoY*		QoQ	YoY*
Bookings (USD)	**874m**	**-0.7%**	**208m**	**-9.1%**	**+4.7%**
Revenue (USD)	**868m**	**-4.2%**	**249m**	**+10.4%**	**+1.4%**
Gross Margin	**31.1%**	**-384 bps**	**31.1%**	**+119 bps**	**-441 bps**

***Period to period variances calculated using HKD**

Key Highlights for Q4 2020:

- Q4 20 Bookings ▼ QoQ, ▲ YoY
    - Despite decline, QoQ Bookings for automotive customers ▲
- Q4 20 Revenue ▲ QoQ and YoY
    - Strong end-market demand for automotive, 5G infrastructure and industrial applications
    - Continued strong demand for high-accuracy SMT systems (AP tools) for SiP applications
    - Strong pickup in equipment services and spare parts business
- Q4 20 GM ▼ YoY, ▲ QoQ
    - Long-term GM improvement with implementation of strategic initiatives

2020 Materials Segment Highlights

(Deconsolidated from FY2021 onwards)

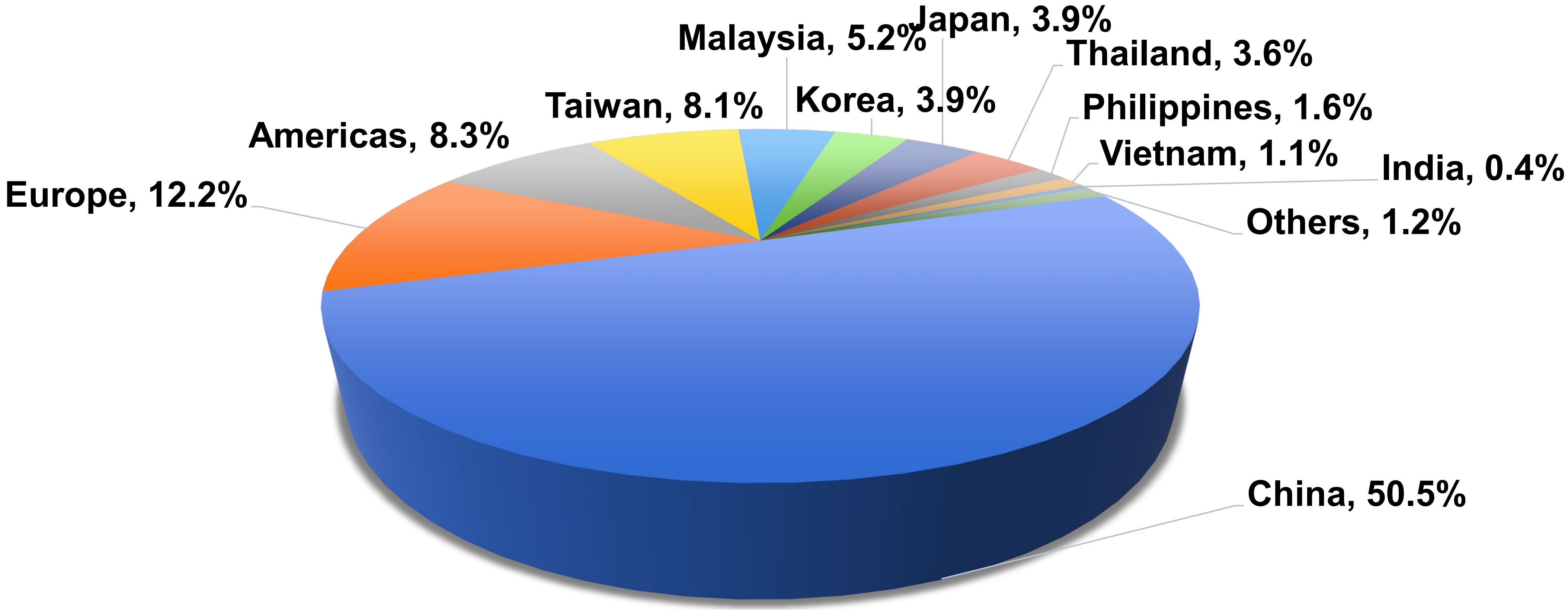
	FY20		Q4 20		
		YoY*		QoQ	YoY*
Bookings (USD)	350m	+45.4%	116m	+75.3%	+64.7%
Revenue (USD)	282m	+18.0%	78m	+1.0%	+17.8%
Gross Margin	15.7%	+558 bps	15.5%	-388 bps	+707 bps

Key Highlights for Q4 2020:

- All-time high quarterly Bookings and Revenue
- Bullish order momentum indicative of robust semiconductor demand
- Q4 20 GM ▲ YoY due to higher volume effect, ▼ QoQ due to operations relocation impacting utilization
- From 29 December 2020, Materials Segment's business will be equity accounted for in the Group's books
- Materials business continues to be of significant strategic importance to Group

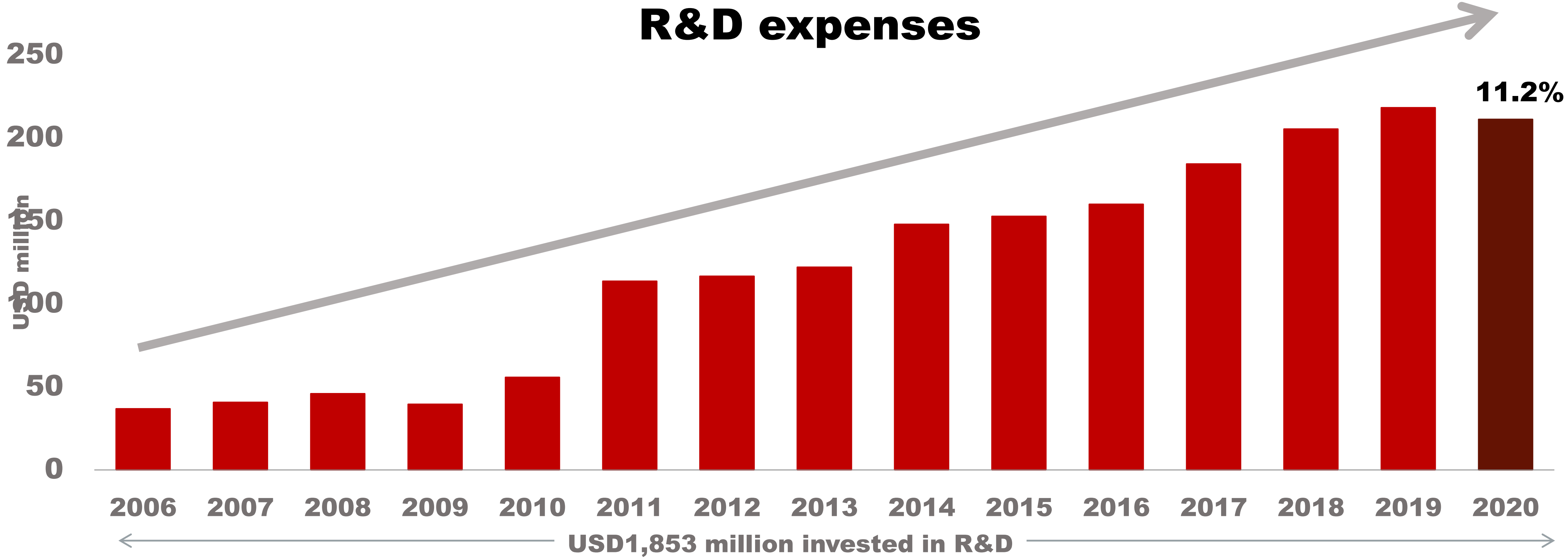
*Period to period variances calculated using HKD

2020 Revenue Breakdown by Geography



Top 5 customers accounted for only 13.7% of Group FY2020 revenue

R&D Commitment Makes Us a Preferred Partner of Choice

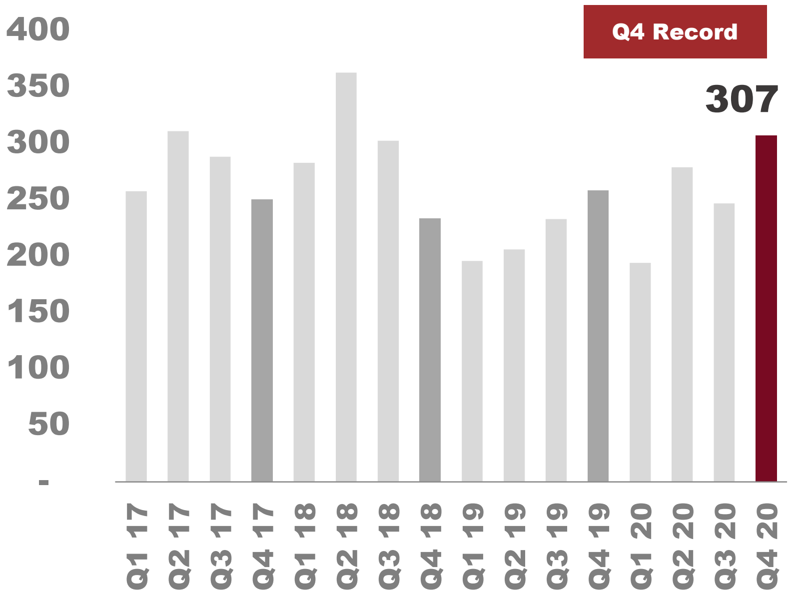


A total of US$211 million invested in R&D expenditure in 2020, equivalent to 11.2% of Equipment Sales.

Business Segments Revenue Trend

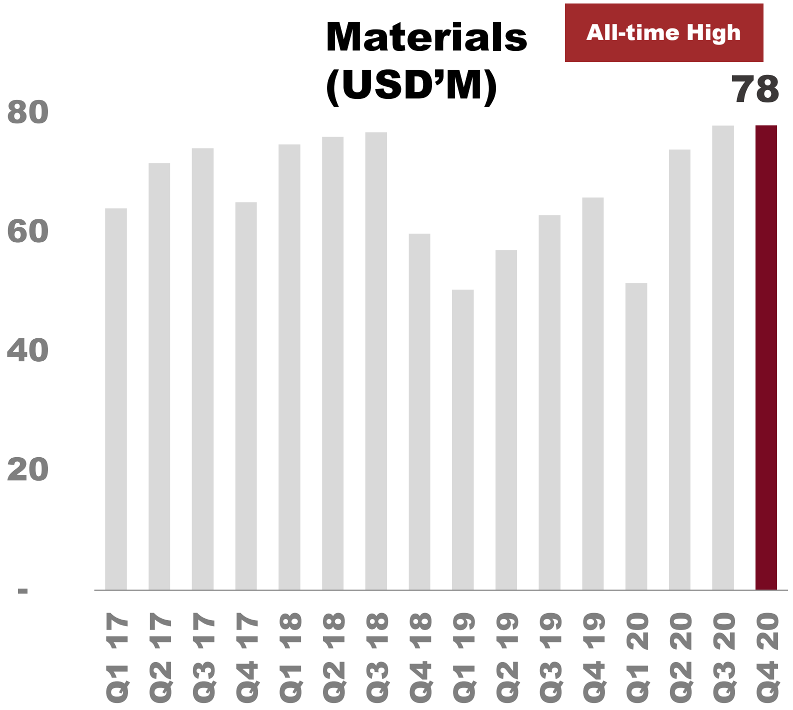
YoY* Growth:
+17.3%

Semiconductor Solutions (USD'M)



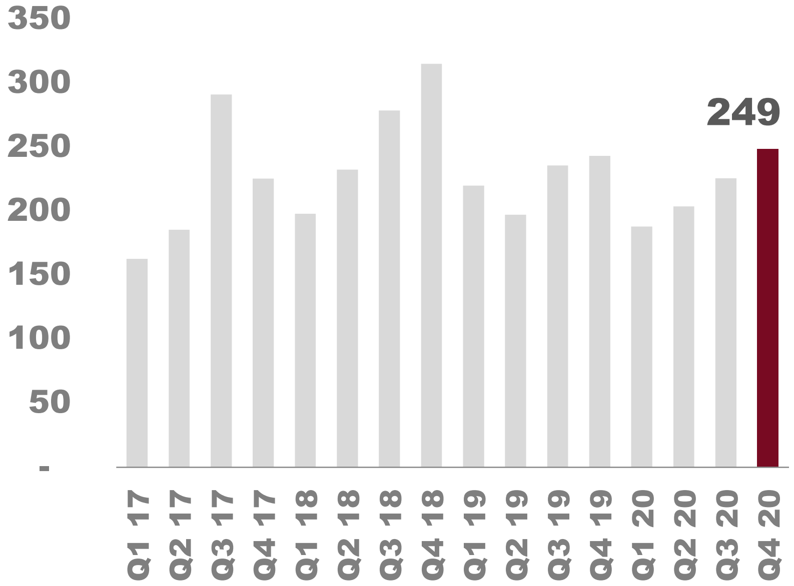
YoY* Growth:
+17.8%

Materials (USD'M)



YoY* Growth:
+1.4%

SMT Solutions (USD'M)



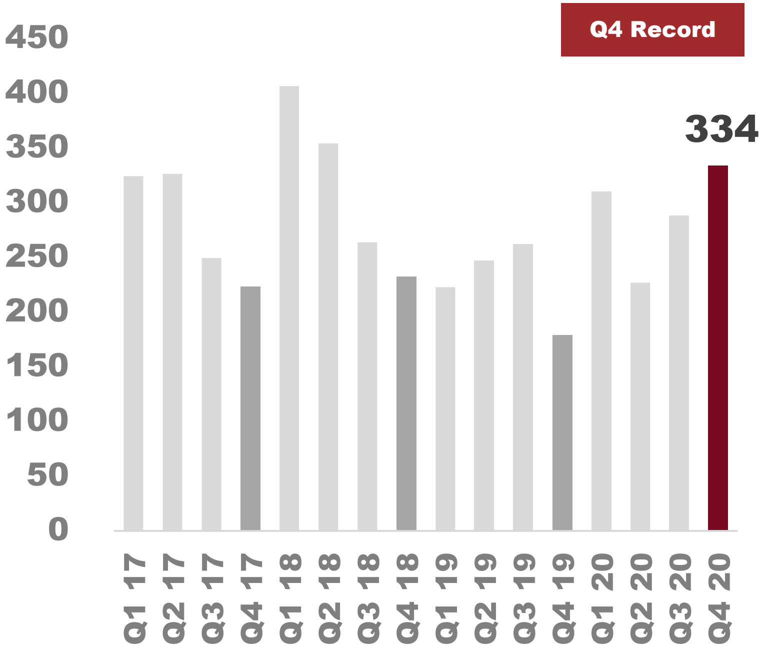
*Period to period variances calculated using HKD

Business Segments Bookings Trend

YoY* Growth:

+84.9%

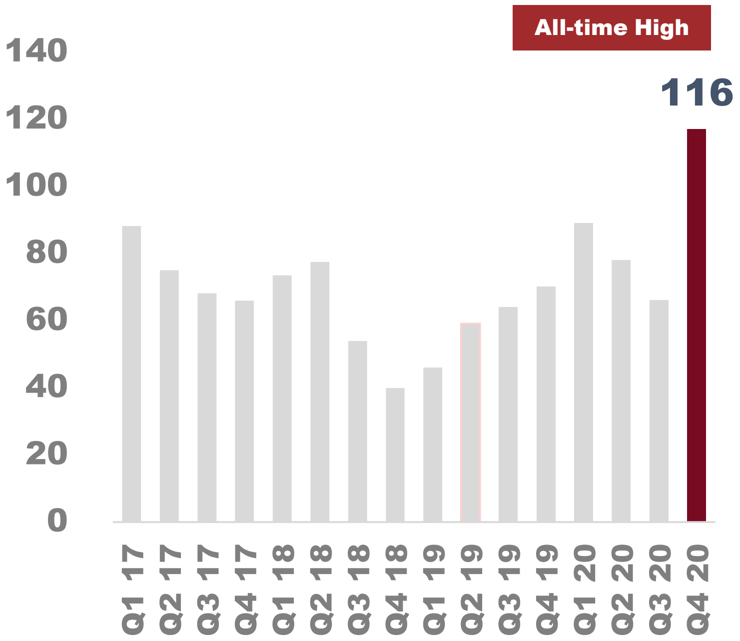
Semiconductor Solutions (USD'M)



YoY* Growth:

+64.7%

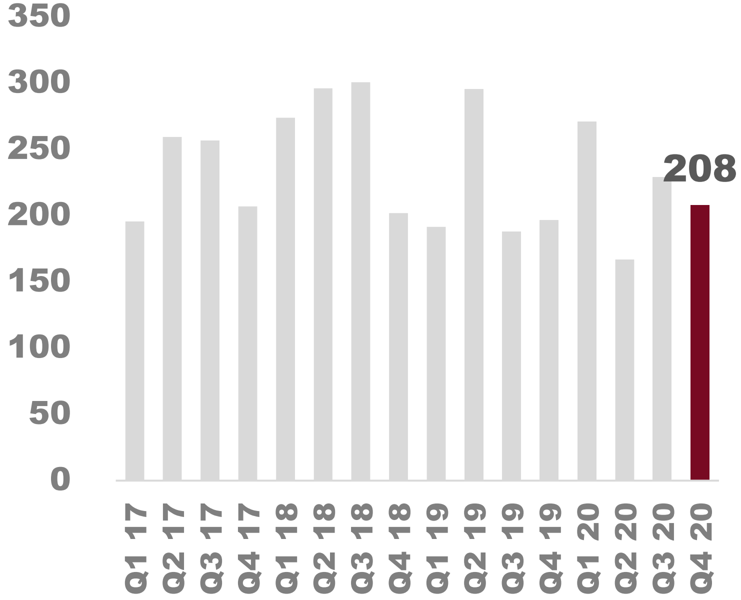
Materials (USD'M)



YoY* Growth:

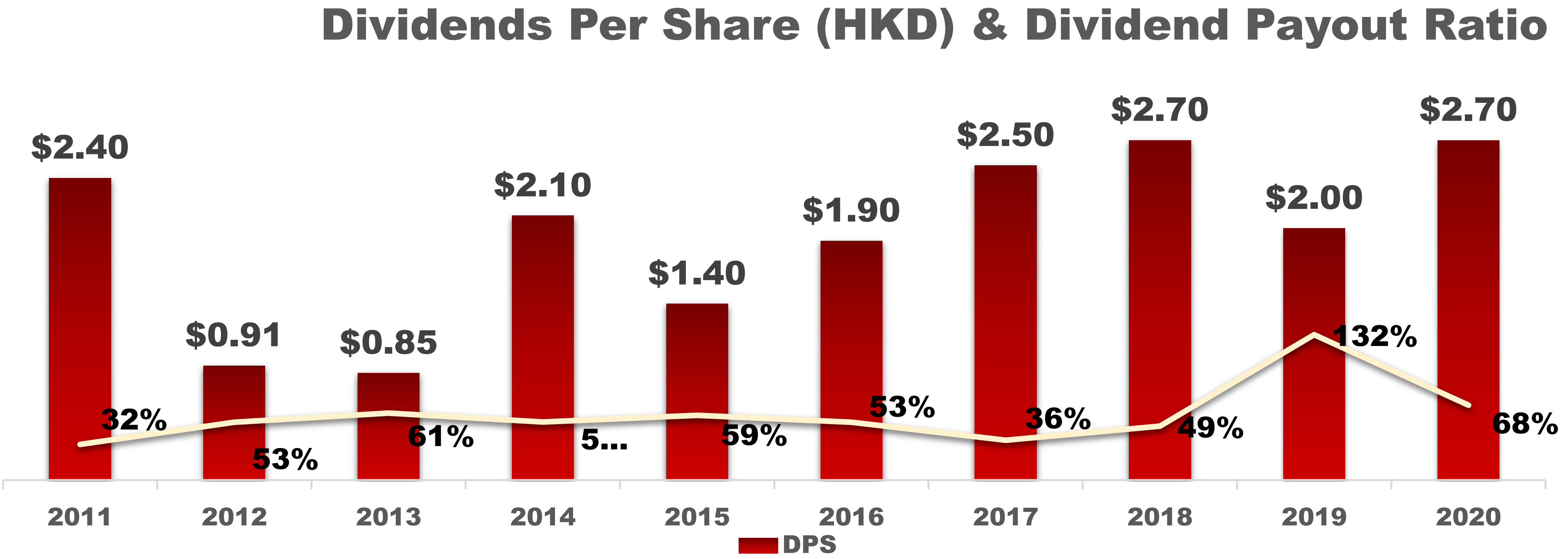
+4.7%

SMT Solutions (USD'M)



*Period to period variances calculated using HKD

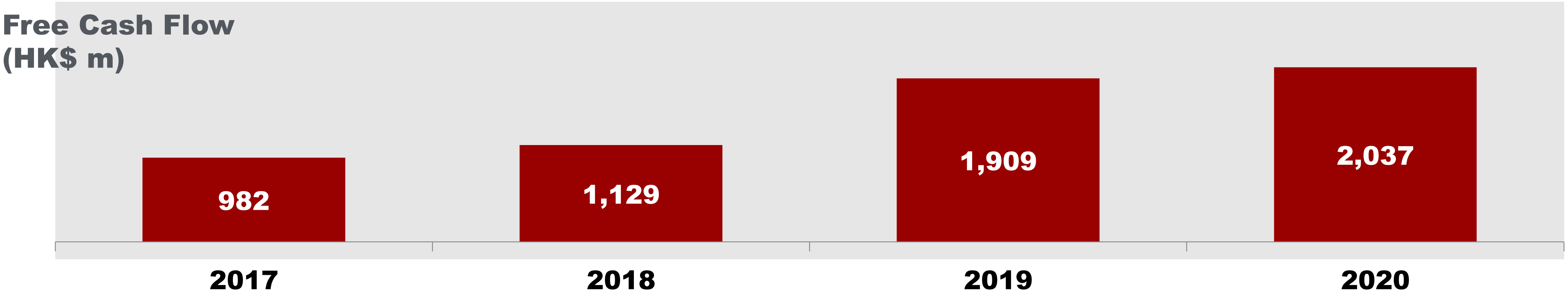
2020 Dividends and Dividend Policy

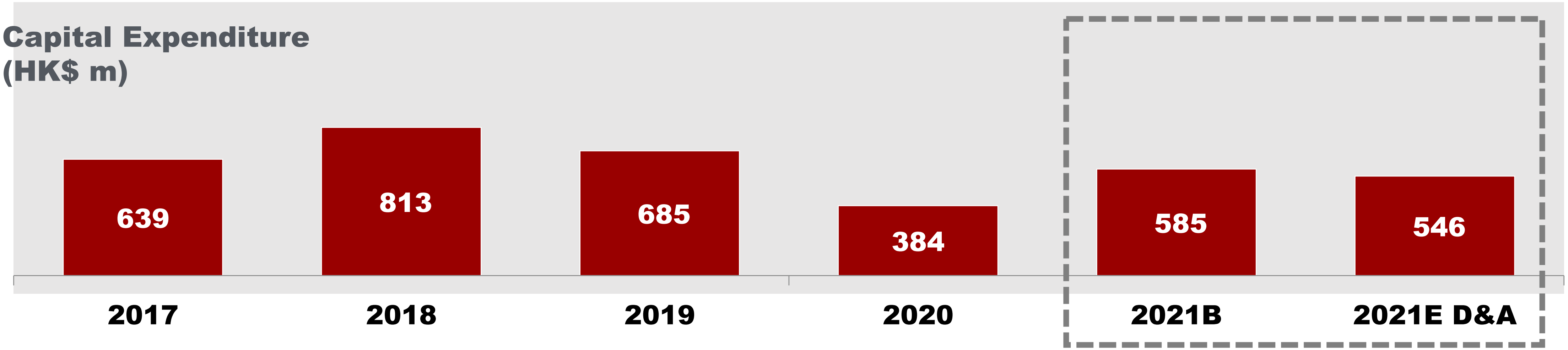


- Consistent dividend payout every year since HKEX listing in 1989
- Above-average dividend payout ratio of 68% in FY 2020 to reward shareholders from the net gain attributable to the one-off items
- Dividend policy of consistent annual dividend payout ratio of around 50% *(consistent with average dividend payout ratio 2011-2020)*

Free Cash Flow and Capital Expenditure

Healthy Free Cash Flows to Support Operational and Investment Plans

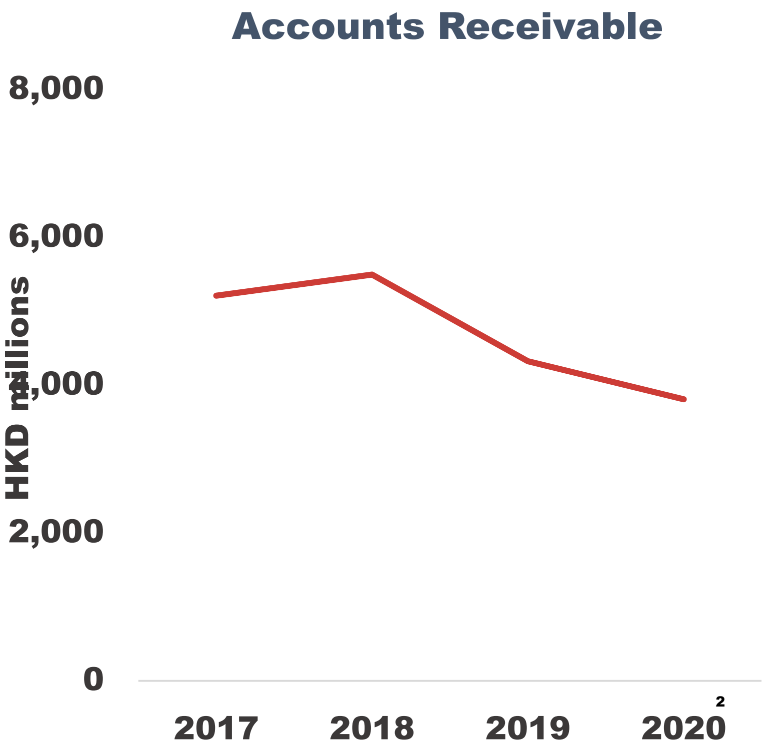


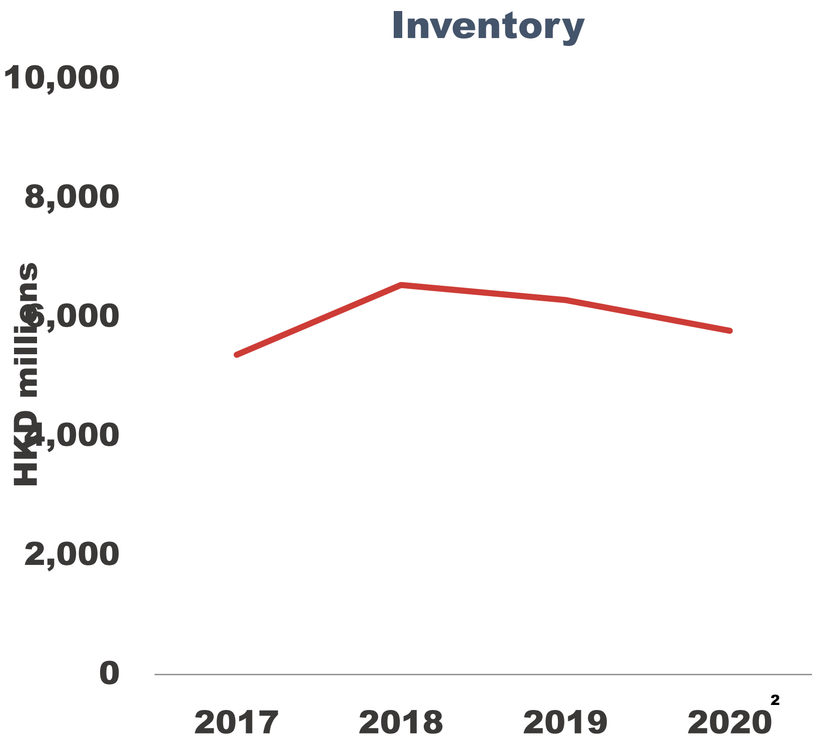


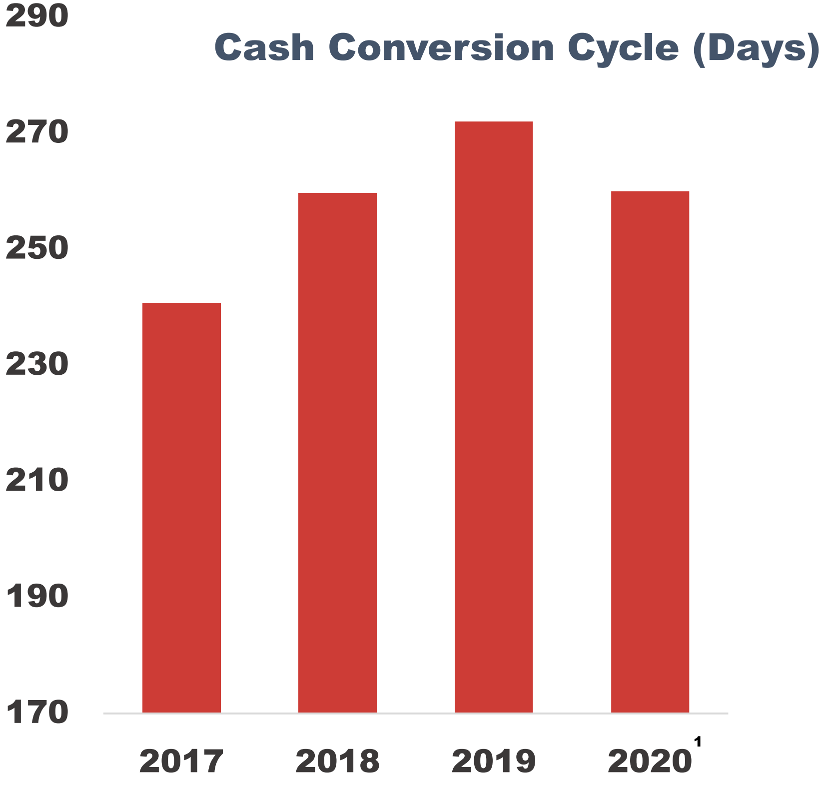
2021 excludes Materials Segment

Working Capital Management

Improving Liquidity and Capital Efficiency



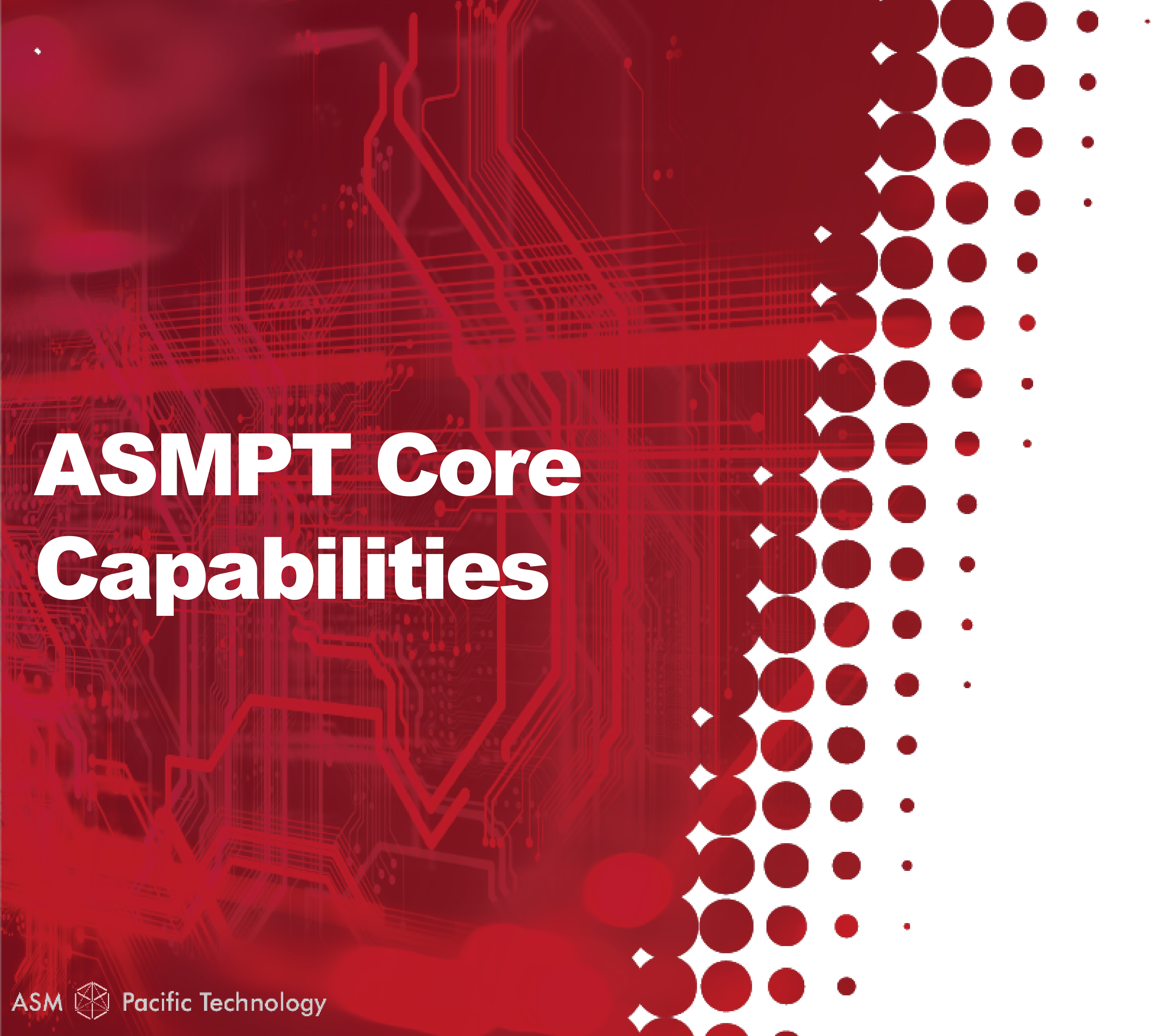




[1] Cash Conversion Cycle computation excludes Materials Segment contribution

[2] A/R and Inventory balances have excluded Materials Segments' contribution

ASMPT Core Capabilities



ASMPT’s Pervasive Presence in Multiple End-Market Applications

Highlighted in This Presentation: Automotive

Mobility, Comm. and IT	Optoelectronics	Automotive	Power Management & Energy	Industrial	Consumer
					
Personal Computers Smartphones 5G Base Stations Micro Cells Datacentres HPC Internet of Things	Virtual Reality Autonomous Vehicles Large Screen Display Smartwatches Security	Visual Sensors Infotainment LIDAR Sensors 5G communications Entertainment Platforms	Electric Vehicles Automotive Power Module Wireless Charging	Smart Factories Smart Offices	Consumer Electronics Wearable Devices Gaming Consoles Fitness Bands

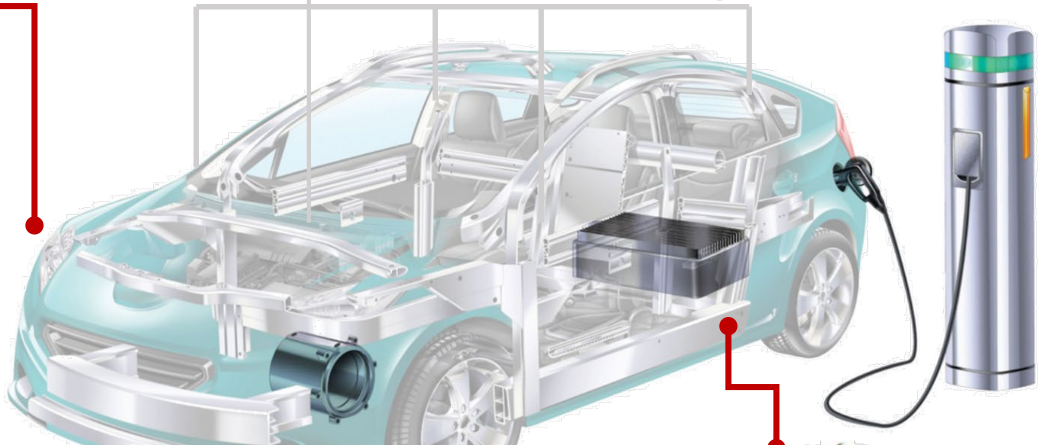
Comprehensive Capabilities

Pervasive use of ASMPT Technology (Automotive Electrification as Example)

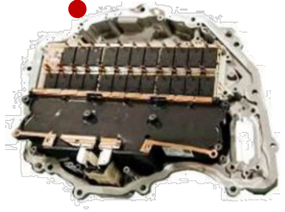
LiDAR

In-Vehicle Infotainment System

Front/Surround/Rear view ADAS cameras



Self-Drive Computing Board



Power Module

Light Emitting Diode (LED) Solutions

Automotive lighting, Infotainment screens

Die / Wire Bonding Solutions

RF modules, Computing board, General electronic devices, V2X communications, Power modules

Advanced Packaging (AP) Solutions

High performance self-driving chips

CMOS Image Sensor (CIS) Solutions

Vehicular camera, LiDAR, Radar, Sensing modules

Surface Mount Technology (SMT) Solutions

Battery management system, Motor control unit, SiP automotive packages

Silver Sintering Solutions

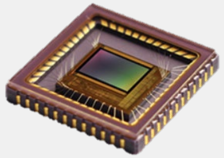
Power modules

Source: Yole Developpement, Sensing and computing for ADAS vehicles, Samsung

Comprehensive Automotive CIS Solutions

Automotive Electrification Demands More Imaging Sensors

1st Level Packaging



A typical CIS Package

CIS Packaging addressed by **SEMI Solutions Segment**

Example of typical CIS Packaging Process highlighted in Appendix

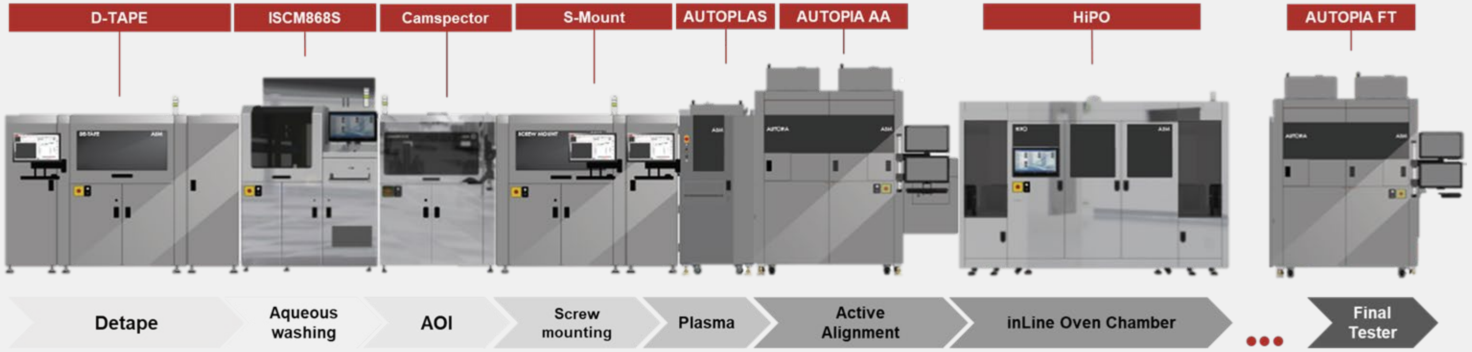
2nd Level Packaging

A typical CIS PCB

CIS PCB Assembly addressed by **SMT Solutions Segment**

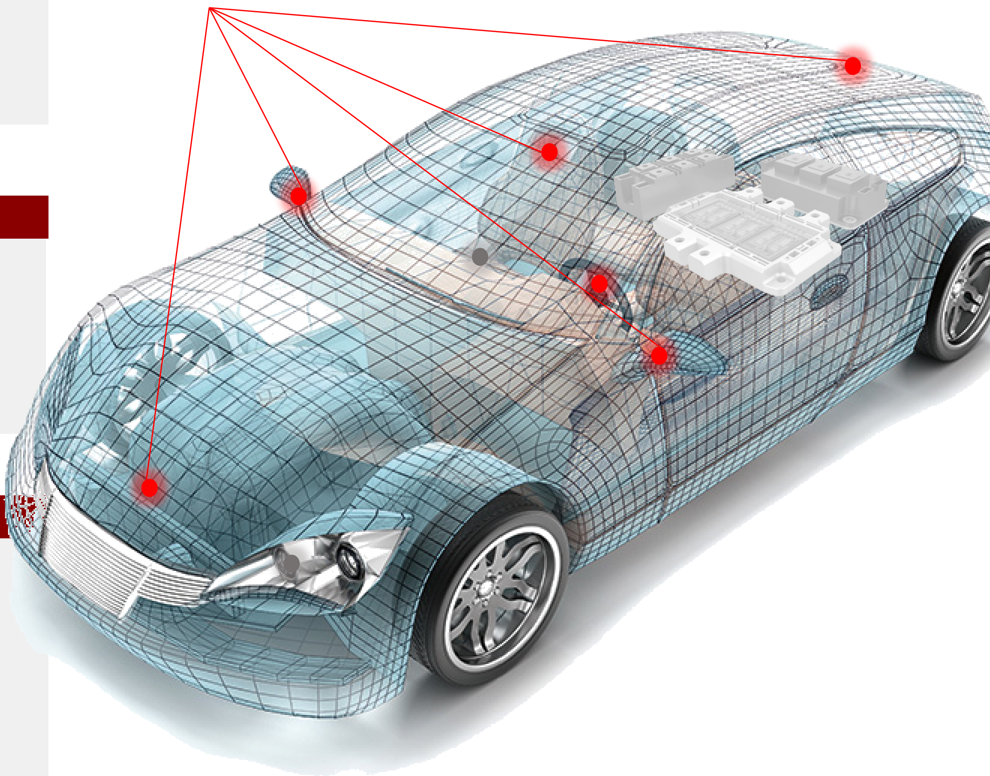
Example of typical 2nd Level Packaging Process highlighted in Appendix

Camera Module Assembly Stage

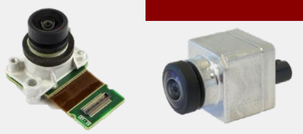


Front / Surround / Rear View Camera

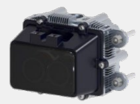
CIS packages, LiDAR modules



Completed Modules



Automotive Camera Module



LiDAR Sensor Module

All round safety: *Cameras and Sensors are deployed 360º, functioning as 'eyes' to vehicles and a key enabler towards L5 autonomous driving*

Comprehensive Total Automotive Power Management Solutions

Automotive Electrification Drives Greater Power Requirements


Wafer Dicing


Curing


Molding

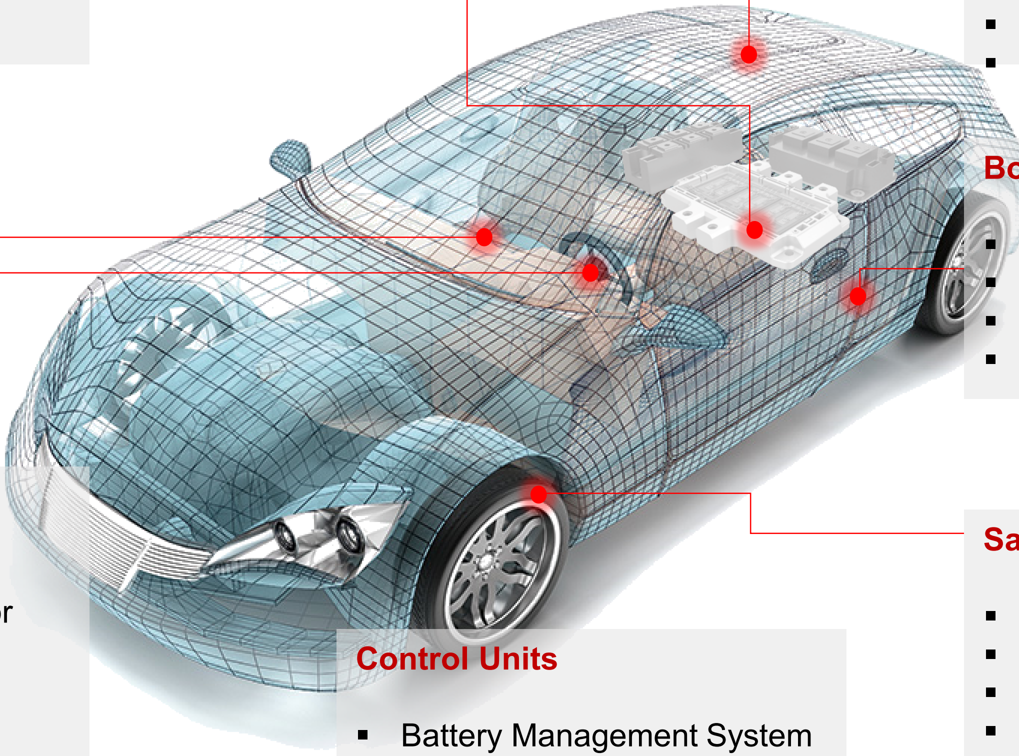

Die Bonding


AgS Printing


Ag Sintering


Automated Optical Inspection

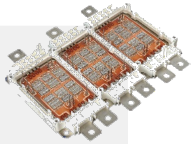

HA Wire Bonder



Infotainment

- Display
- Entertainment Centre
- Navigation
- Instrumentation

Powertrain



- Invertors
- Rapid Charging

Camera Module

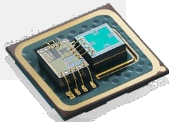
- Display
- Entertainment Centre
- Navigation
- Instrumentation

Body Electronics

- Interior Lighting
- Power Windows
- Power Seats
- Sunroof

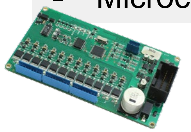
MEMS & Sensors

- Accelerometers
- Pressure Sensor
- Comfort Control System
- Light Dimmer
- Pedestrian Detection



Control Units

- Battery Management System
- Motor Control Unit
- Microcontroller



Safety Systems

- Air Bag System
- Braking System
- Entry Security Alarm
- Collision Warning
- Driver Drowsiness Monitor

Comprehensive Advanced Packaging Solutions for Automotive

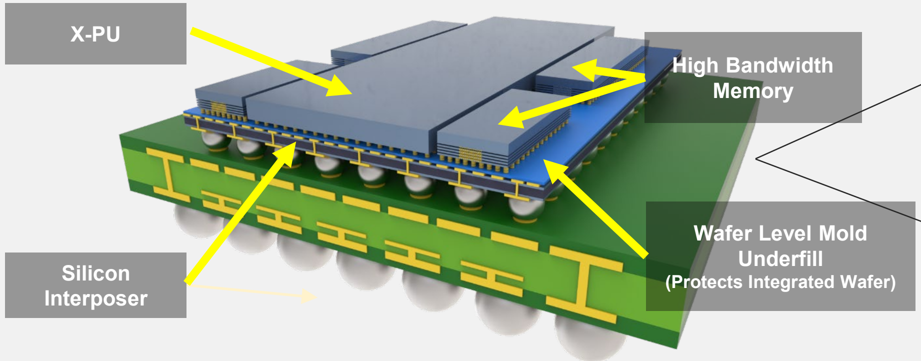
Driven by Economic Advantages Compared with Pure Silicon Scaling

Advanced Packaging Technology Enabler

FIREBIRD
TCB
FLI

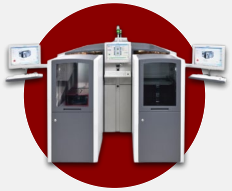
NEXX
PVD | ECD
Bumping,TSV & RDL

ORCAS
Encapsulation
Wafer and Panel



A typical Heterogeneous Integration Packaged Chip

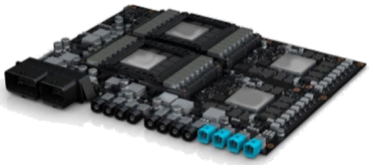
Laser1205
Laser Separation
Wafer Dicing and Grooving



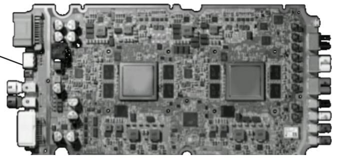
SIPLACE CA
DIE ATTACH & SMT
Wafer and SMT Feeders

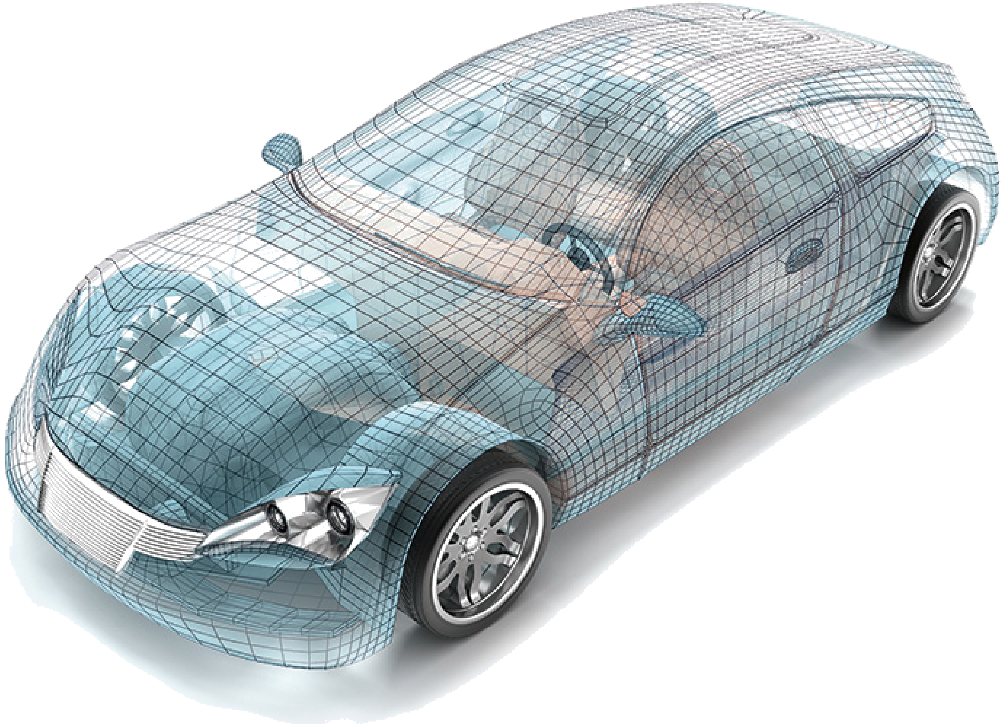
NUCLEUS
Pick and Place
Wafer and Panel

A Computing Board with 4 High Performance AI Processors



A Computing Board with 2 High Performance Self-Driving AI Chips

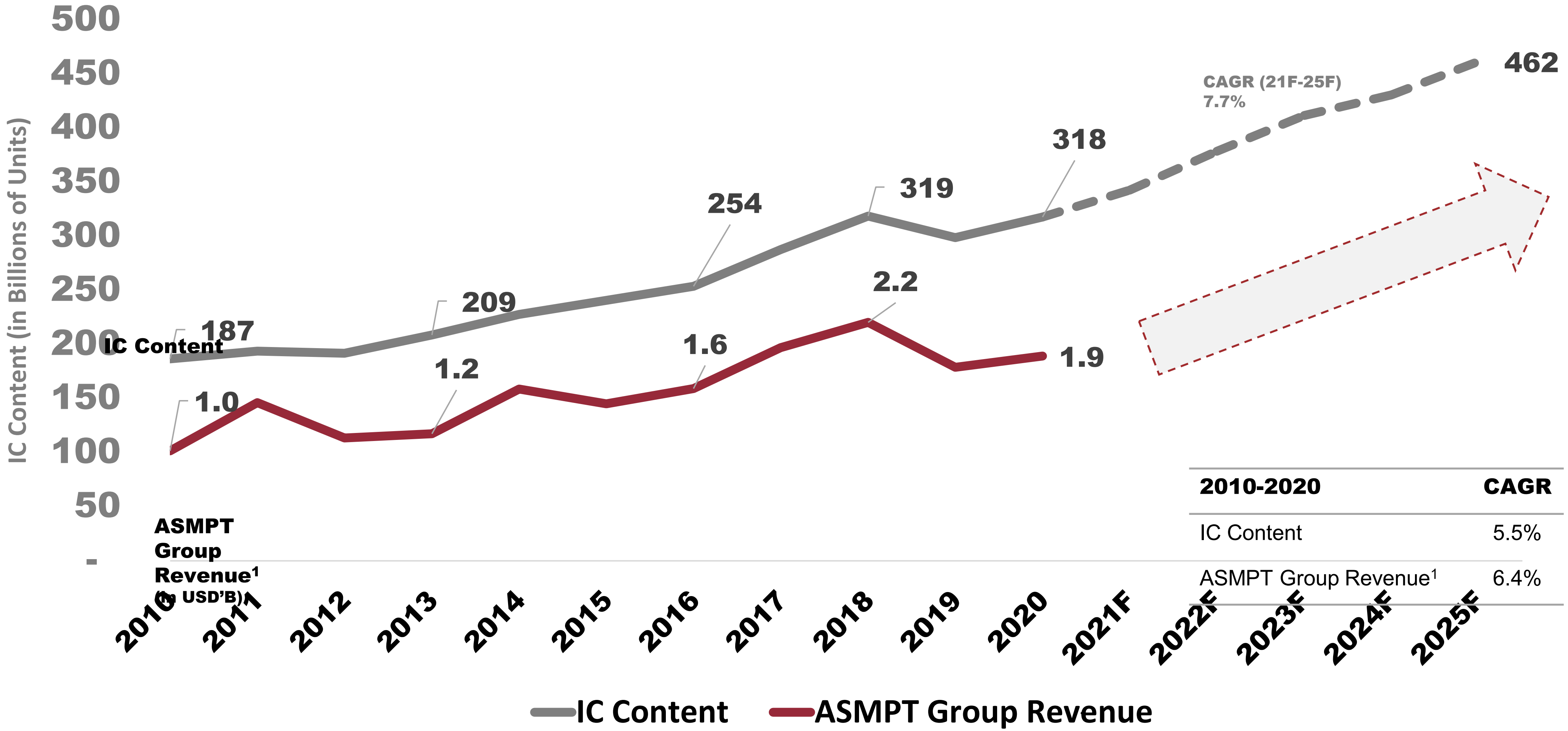




Growth Drivers

Growing in Tandem with IC Content Produced Over the Years

Broader Semiconductor Growth from Megatrends Bode Well for ASMPT's Growth



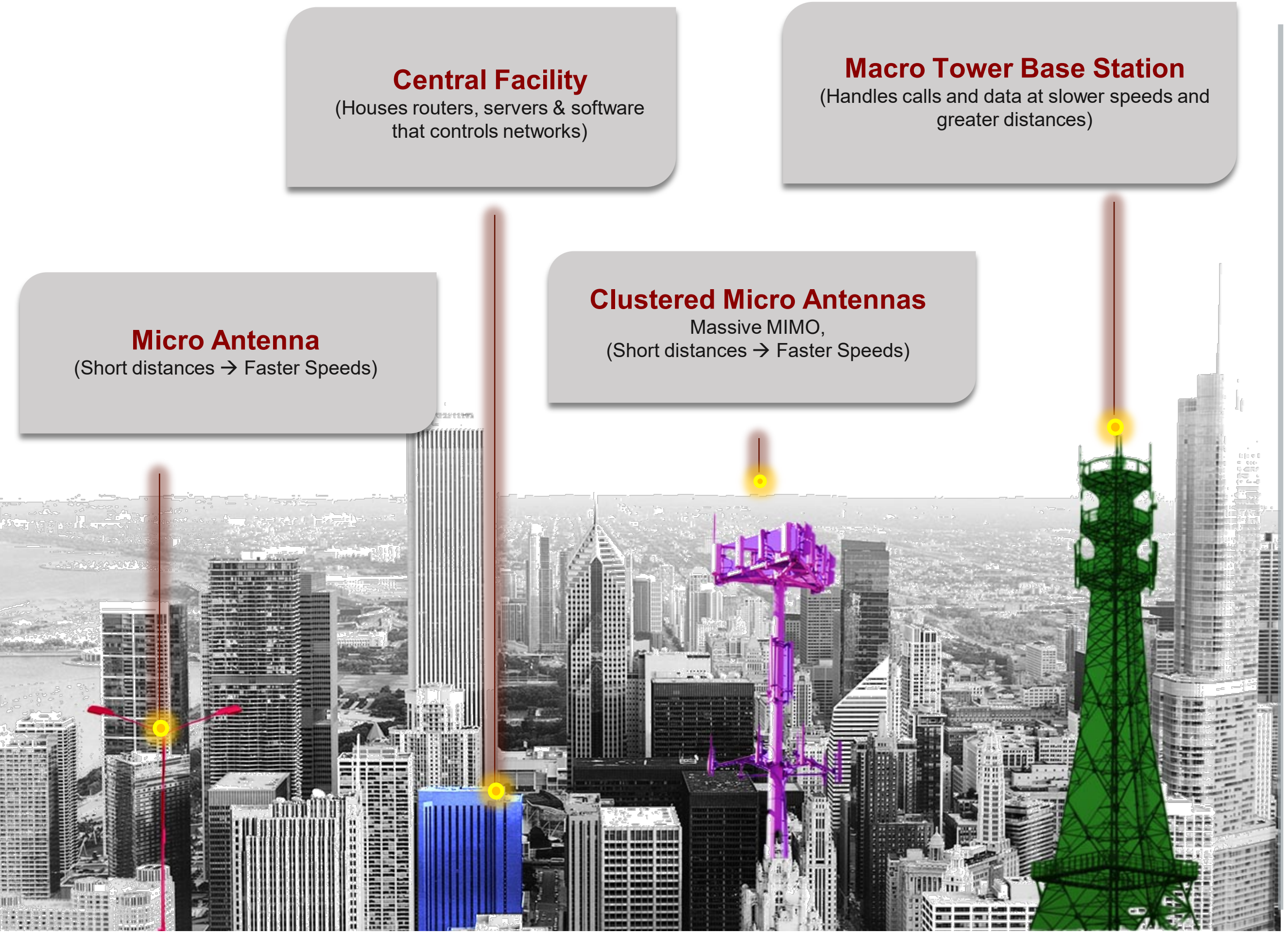
2010-2020	CAGR
IC Content	5.5%
ASMPT Group Revenue¹	6.4%

Source : VLSIresearch, Management Estimates

[1] ASMPT Group Revenue excludes Materials Segment Contribution

Market Growth Driver – 5G Infrastructure

Multi-Country, Multi-Year Driver from 5G Rollout



Central Facility
(Houses routers, servers & software that controls networks)

Macro Tower Base Station
(Handles calls and data at slower speeds and greater distances)

Clustered Micro Antennas
Massive MIMO,
(Short distances → Faster Speeds)

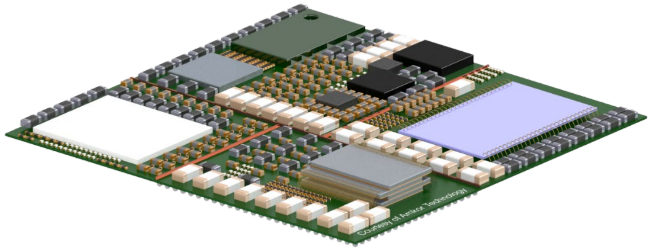
Micro Antenna
(Short distances → Faster Speeds)

rivers for Equipment Capacity Buys

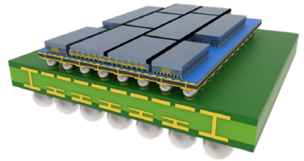
	4G Base Station	5G Base Station	Increase
Power Amplifiers	12 per Cell	96 to 192 per Cell	8x to 16x

rivers for Equipment Capability Buys

System in Package



Advanced Packaging



Source : Semiconductor Engineering

Market Growth Driver – 5G Smartphones

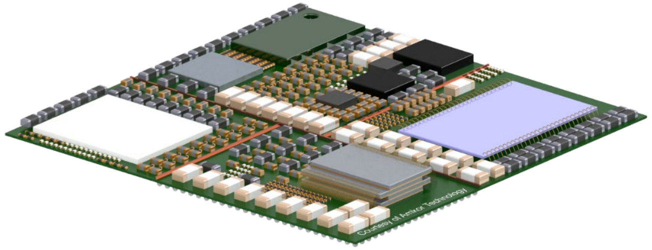
Greater Demand for Higher Performance End Devices

Drivers for Equipment Capacity Buys

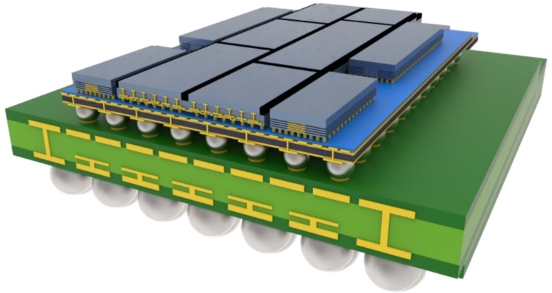
	4G	5G	Increase
Filters:	40	70	1.75x
Bands:	15	30	2.0x
Tx/Rx Filters:	30	75	2.5x
Switch Throws:	10	30	3.0x
CA Combos:	10	200	20.0x
Sensors:	6	7	1.17x
Camera Module:	5	7	1.4x
Microphone:	2	3	1.5x

Drivers for Equipment Capability Buys

System in Package



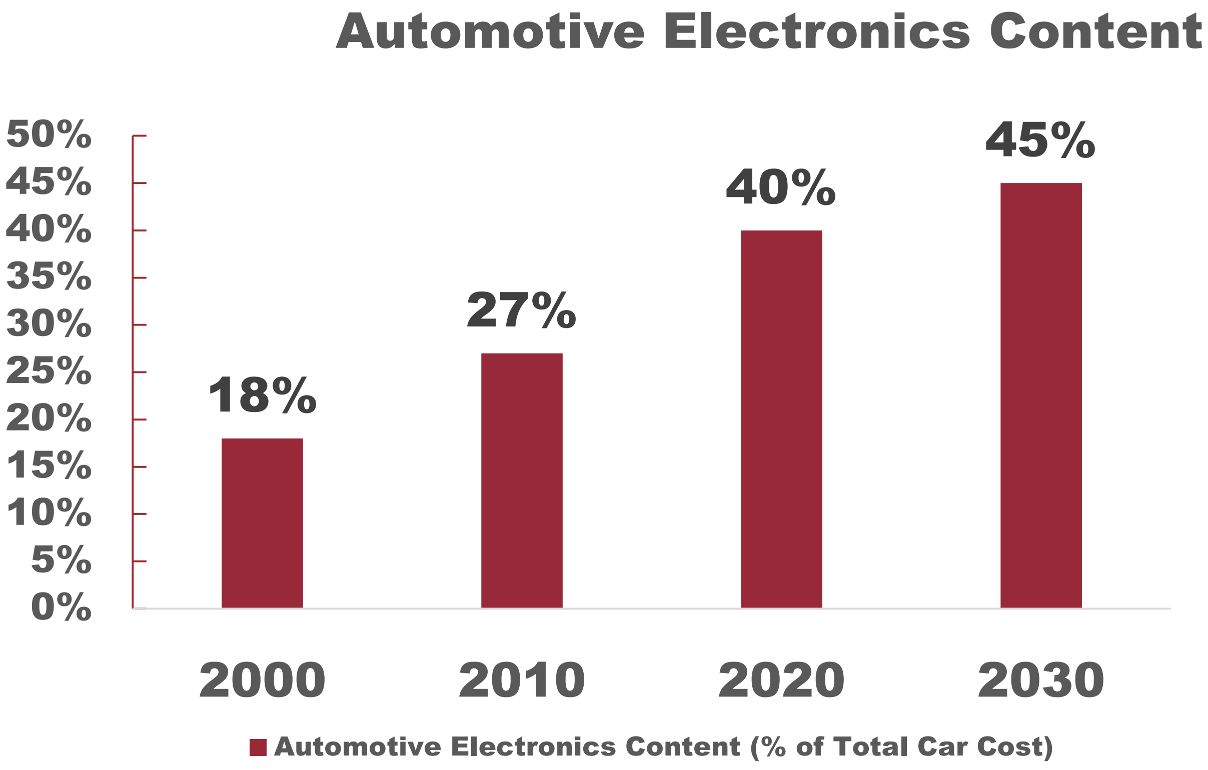
Advanced Packaging



Source: Skyworks Presentation, Huawei P30 Pro, P40 Pro+, iPhone product spec, management estimates

Market Growth Driver – Automotive Electrification

Increasing Automotive Electronics Content Expands ASMPT's Market



Source: Deloitte

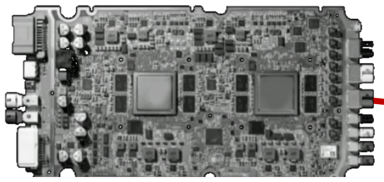
rivers for Equipment Capacity Buys

	Present	Future	
	Level 2 Autonomy	Level 5 Autonomy	Increase
ADAS camera	**X 1**	**X 9**	**9x**
LiDAR	**-**	**X 5**	**5x**
Other Sensing Modules	**X 17**	**X 22**	**1.3x**

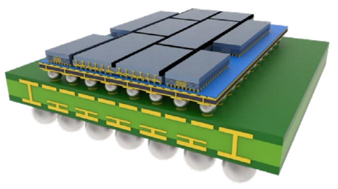
rivers for Equipment Capability Buys

	Present	Future	
	Level 2 Autonomy	Level 5 Autonomy	Increase
Computing Power	**0.25 TOPS**	**1,000 TOPS**	**4,000x**

TOPS: Tera Operations per Second. A measure of maximum achievable throughput



Computing Board with High Performance Self-Driving Chip



Advanced Packaging

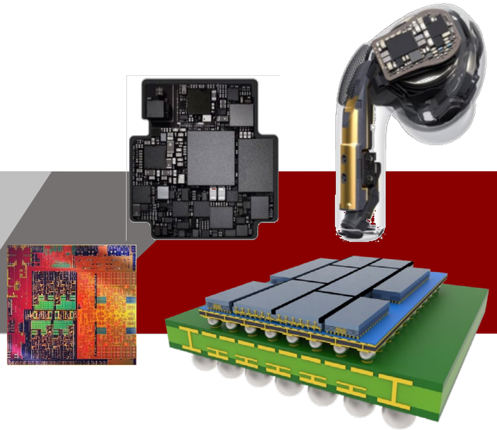
Source: Yole Developpement, Sensing and computing for ADAS vehicles

ASMPT Growth Enablers

Well Positioned to Capture Growth

Automotive and Power Solutions

Comprehensive suite of Automotive Electrification Solutions



Advanced Packaging Solutions (AP)

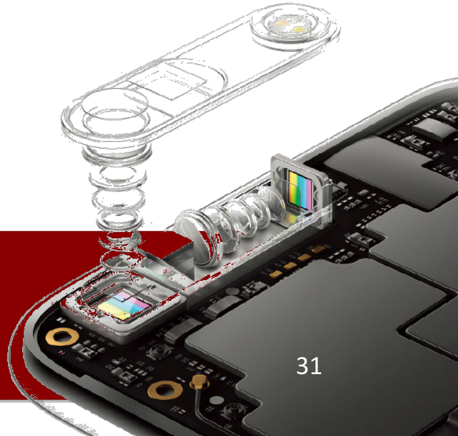
Comprehensive suite of AP Solutions

Light Emitting Diode Solutions (LED)

Deep engagement with key mini and micro LED customers

Silicon Photonics Solutions

Sub-micron placement accuracy bonding capabilities



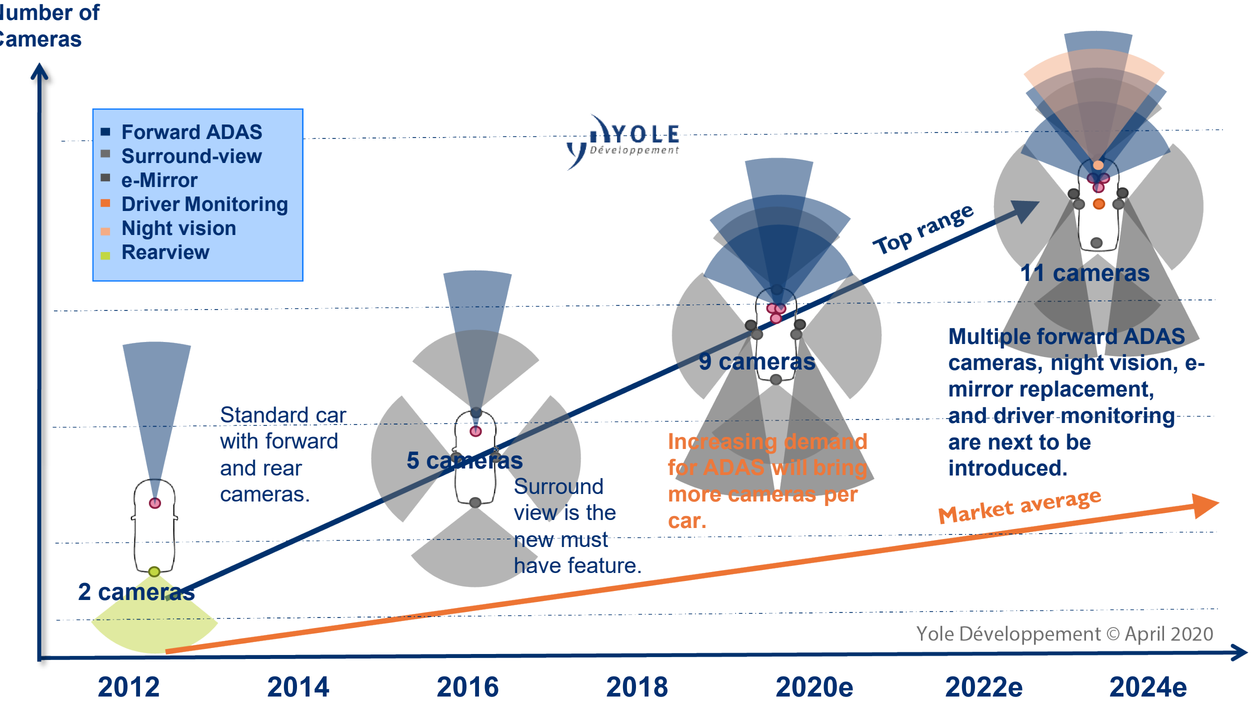
CIS Solutions

Automatic in-line solutions capabilities

Market Enabler – Automotive Electrification

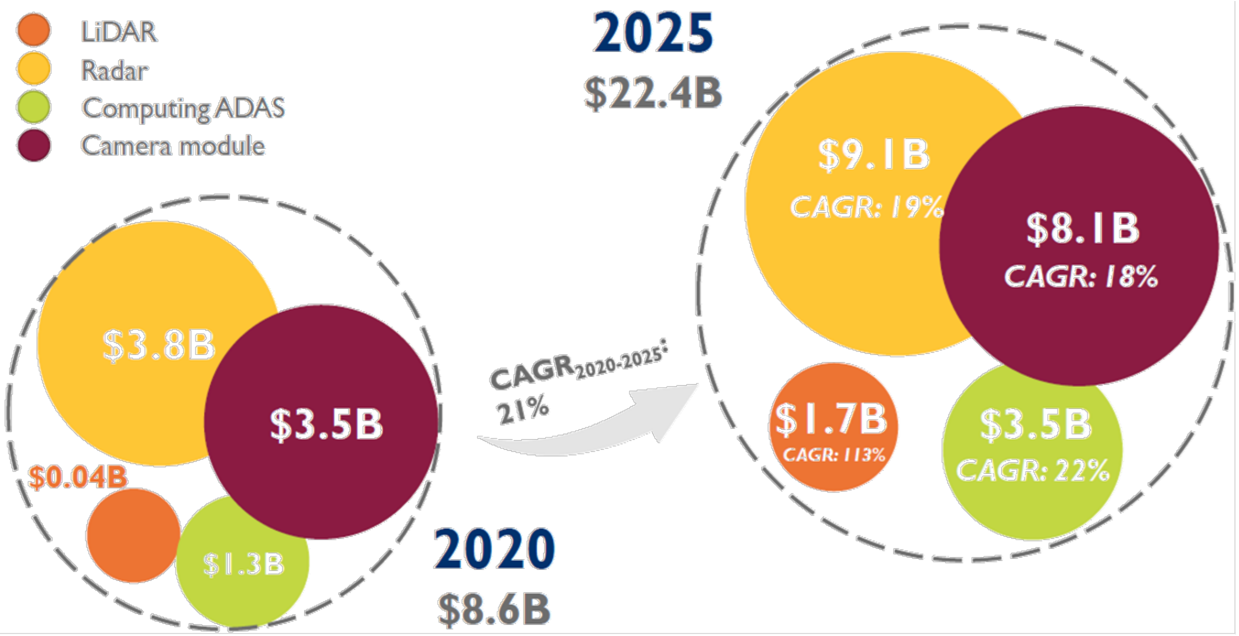
Growing Sensor and Computing Market Revenue

Camera Proliferation in Automotive Development



Yole Développement © April 2020

Increasing Adoption of Sensor and Computing Technologies to Improve Vehicle Safety and Intelligence



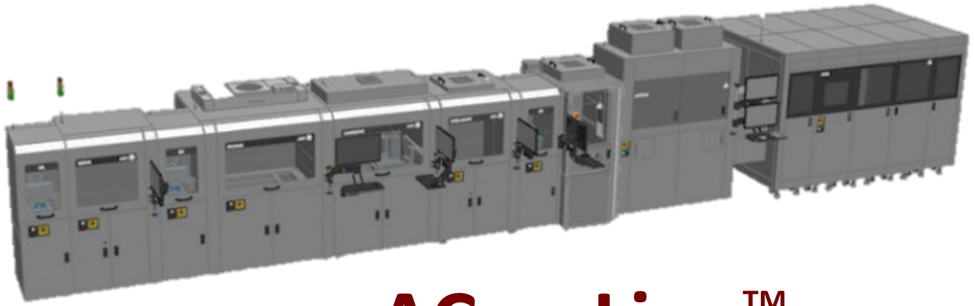
Source: Yole Developpement 2020

ASMPT Automotive CIS Solutions

Comprehensive Solutions for Automotive Market

AUTOPIA

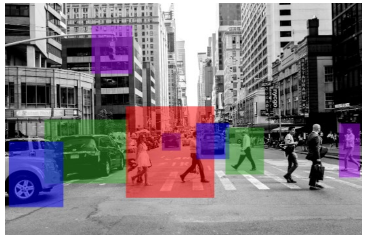
An Innovation for Camera Precision Alignment and Testing



ACamLine™

(Automotive Camera Assembly Solution)

	Levels of Autonomy	Present		Future
		Level 1	Level 2	Level 5
End Market Applications	Viewing Camera	✓	✓	✓
	ADAS Camera		✓	✓
	LiDAR			✓



LiDAR

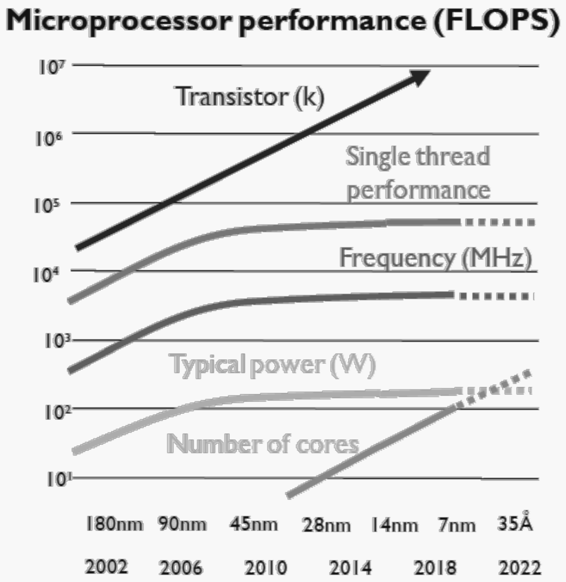
Viewing and ADAS Camera

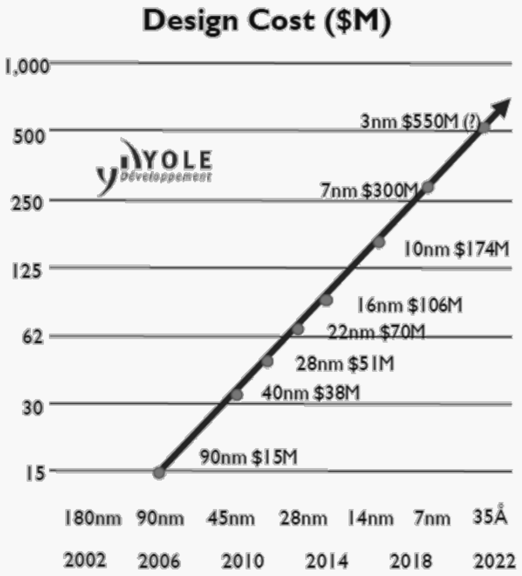
Source: Yole Developpement, Sensing and computing for ADAS vehicles

Market Enabler – Advanced Packaging

Fuelled by Need to Enhance System Performance, Reduce Design Costs and Shorten Time to Market

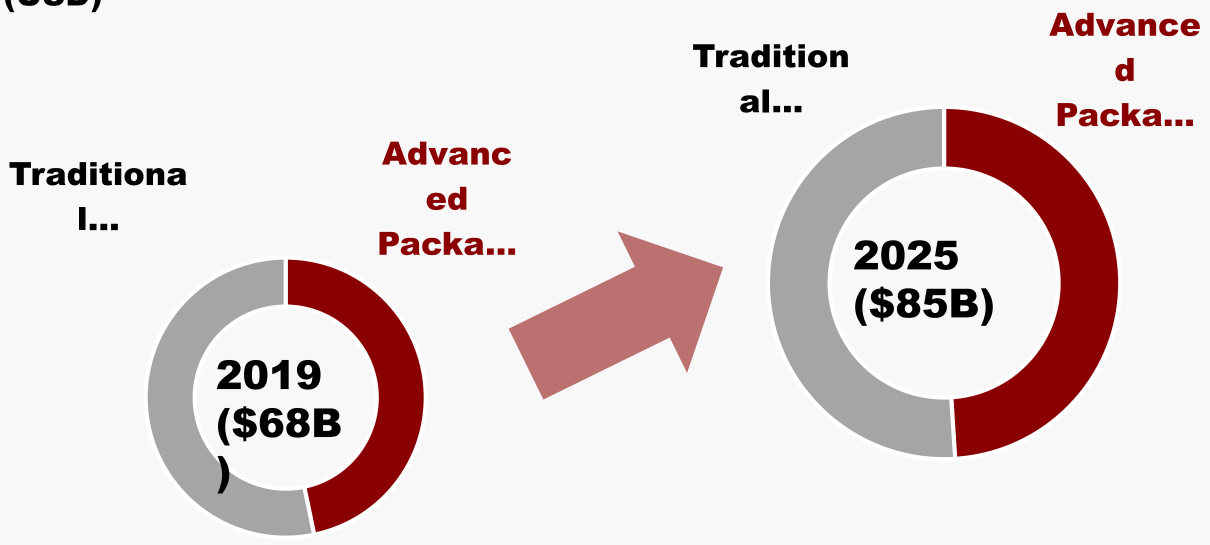
Design costs continue to increase with greater demand for improved device functionality and performance





Increasing AP trend: Adoption of AP technologies in design and manufacturing will reduce cost and time to market

Packaging Revenue (USD)



AP Revenue Contribution **$29B**

AP Revenue Contribution **$42B**

Source: Yole Developpement 2020

ASMPT Advanced Packaging Solutions

Poised to Capture Advanced Packaging Opportunities with Comprehensive Suite of Solutions

Now

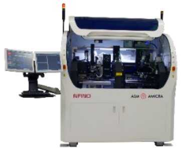
- **Electric Vehicles**
- **Wearables**
- **5G Infrastructure**
- **Data Centres**

\+

Emerging

- **High Performance Computing**
- **Connected Homes**
- **Autonomous Vehicles**
- **Telemedicine**
- **Artificial Intelligence**
- **Factory Robotics**

Markets Enabled By ASMPT's Advanced Packaging Solutions

Advanced Packaging Processes	Physical Vapor Deposition	Electro-Chemical Deposition – Wafer/Panel Lvl Plating	Laser Dicing	Wafer/ Panel Lvl Molding	Wafer/ Panel Lvl Fan Out	Ultra Precision Die Bonding (Silicon Photonics)	Mass Transfer (Mini/Micro LED)	Multi-Chip Module Bonding	Thermo Compression Bonding	Flip Chip	Wafer Level Fan In	SMT SiP Placement	Hybrid Bonding
ASMPT Solutions													Coming Soon in 2021
	Conductor	Stratus Series	Laser 1205	ORCAS	NUCLEUS	NANO	AD300 Series	VECTOR	FIREBIRD	AD8312FC	SUNBIRD	SIPLACE TX Micron	

Market Enabler - Mini and Micro LED

Mini LED

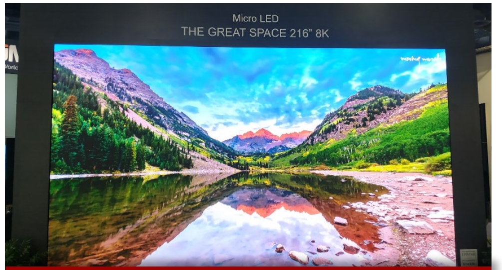
Medium to Large RGB / BLU Display

Market Size CAGR (2020 – 2025)

~ 47%

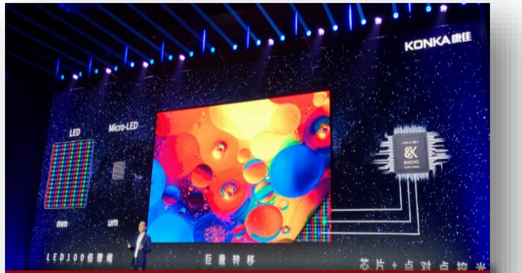
Source: Marketwatch, Jan 2021

TCL
(CES - 2021)



LEYARD
(CES - 2020)

CEDAR ELECTRONICS
(InfoComm - 2019)



KONKA
(KONKA Conference - 2019)

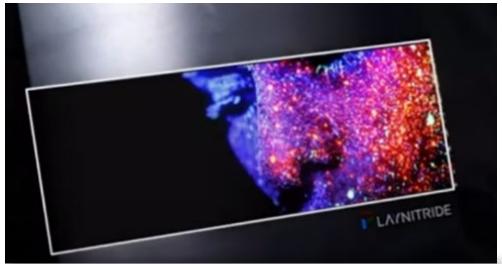
Micro LED

Small Gadget & Transparent Display

Market Size CAGR (2020 – 2026)

~ 116%

Source: Marketwatch, Dec 2020



PlayNitride
(SID - 2020)

TIANMA
(UDE - 2020)

AUO
SID - 2020

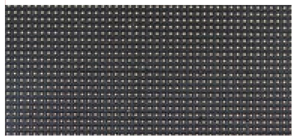
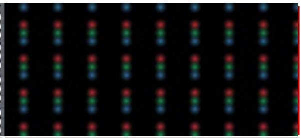
Samsung
(CES - 2021)

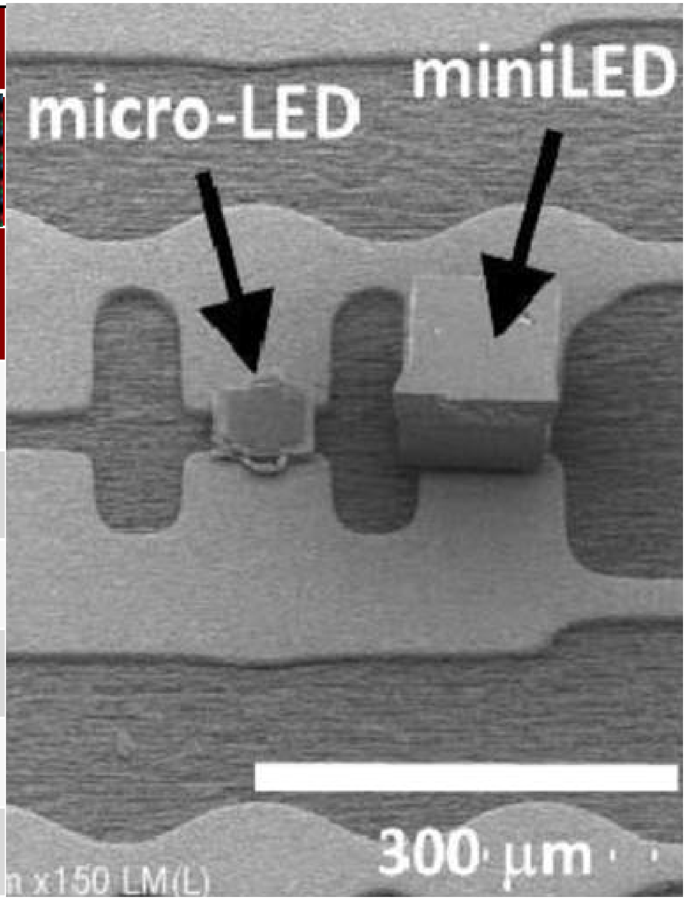
Source: Photos of displays from various conferences

ASMPT Mini & Micro LED Solutions

Ocean Line: Fully Automatic Production Line for Micro LED

Inline Linker: Fully Automatic Production line for Mini LED

	Processes	Conventional	Mini LED	Micro LED
				
	Pitch Size Die Size	1.0mm to 10mm 75µm– 200µm	0.3mm to 1.0mm 50µm – 100µm	0.2mm <50µm
End Market Applications	Digital Display	✓	✓	✓
	Television		✓	✓
	Automotive		✓	✓
	AR/VR			✓
	Wearable			✓
	Mobile			✓



Market Enabler – Silicon Photonics

Enabling Faster Data Bandwidth and Speed Transmission

Data Centres

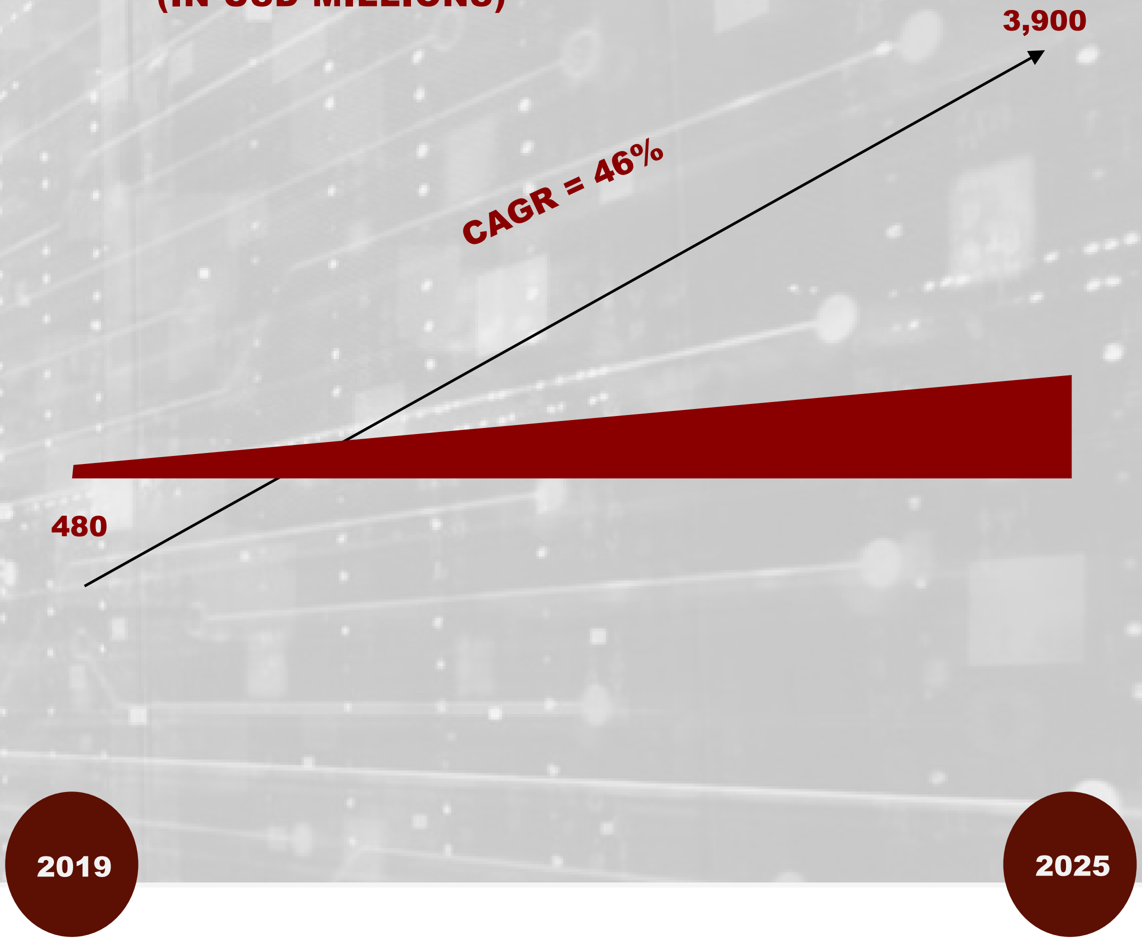
10X

Higher Data Transmission Speed

4X

Greater Bandwidth
100gbps ► 400gbps

SI PHOTONICS MARKET SIZE (IN USD MILLIONS)



Source: Yole Developpement Silicon Photonics Market and Technology Report, May 2020

ASMPT Silicon Photonics Solutions

	Processes	Photonics	Silicon Photonics
	Placement Accuracy **Die Size**	2 – 10µm 150µm – 2000µm	0.3 – 2.0 µm 150µm – 3000µm
End Market Applications	**Data Centre-Cloud**	✓	✓
	Telecom - 5G	✓	✓
	3D Sensing	✓	
	LiDAR	✓	✓

Outlook

Outlook

Q1 2021 Group Revenue Guidance

- Q1 2021 Group Revenue range **US$500m – US$550m**, a Q1 quarterly record (excluding revenue from Materials Segment)
- SEMI Segment is expected to deliver strong QoQ revenue growth, offset by a QoQ seasonal decrease in SMT Segment revenue
- The Group has aggressively ramped up its capacity to meet delivery commitments to customers over the coming quarters.

Q1 2021 Group Bookings Guidance

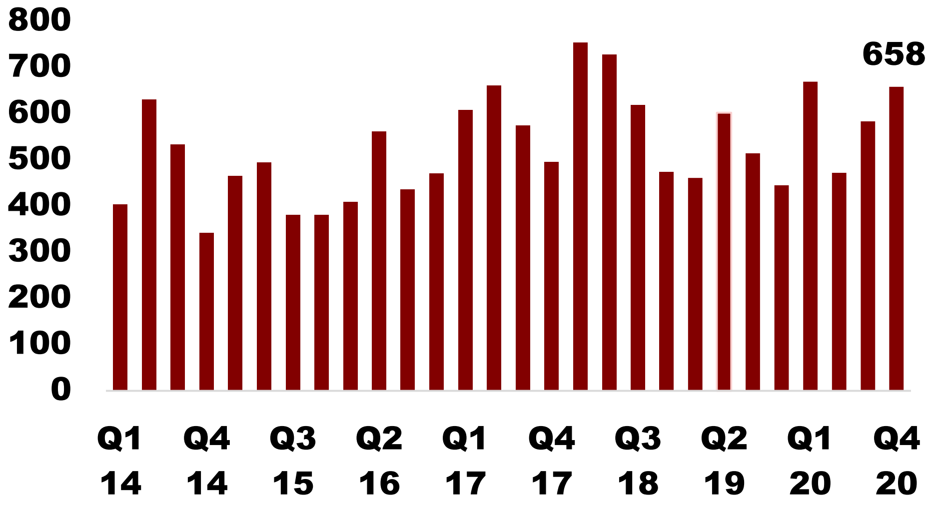
- Q1 2021 Group Bookings are expected to surpass **US$700m** (excluding Materials Segment)
- Since the beginning of 2021, the Semiconductor Solutions Segment experienced order intake momentum at an unprecedented pace

Other 2020 Financial Information

2020 Group Bookings

YoY* Growth:

+46.3%



	Q4 2020 Bookings			2020 Bookings	
	USD	YoY*	QoQ*	USD	YoY*
Group	**658m**	**+46.3%**	**+12.9%**	**2,382m**	**+16.7%**
Semi Solutions Segment	**334m**	**+84.9%**	**+16.0%**	**1,158m**	**+25.9%**
SMT Solutions Segment	**208m**	**+4.7%**	**-9.1%**	**874m**	**-0.7%**
Materials Segment[1]	**116m**	**+64.7%**	**+75.3%**	**350m**	**+45.4%**

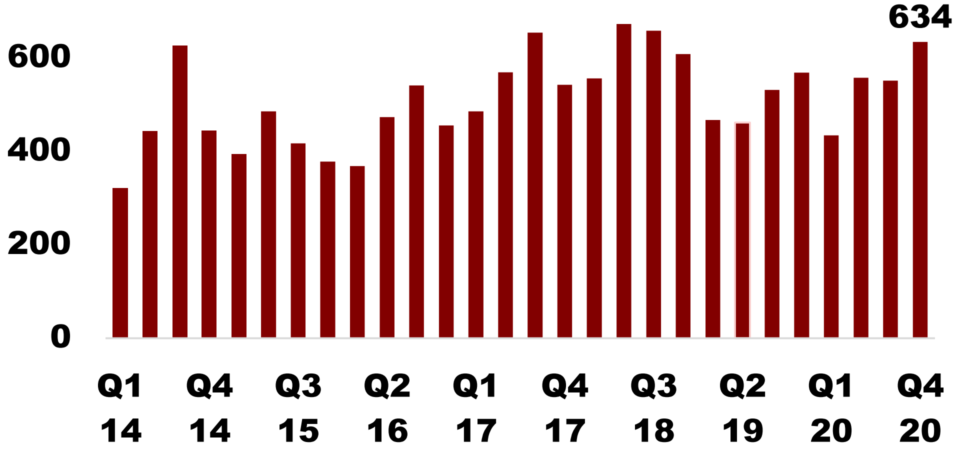
[1] Materials Segment will be de-consolidated and equity accounted for from 29 December 2020

*Period to period variances calculated using HKD

2020 Group Revenue

YoY* Growth:

+10.5%



	Q4 2020 Revenue			2020 Revenue	
	USD	YoY*	QoQ*	USD	YoY*
Group	634m	+10.5%	+15.2%	2,177m	+6.3%
Semi Solutions Segment	307m	+17.3%	+24.1%	1,027m	+13.8%
SMT Solutions Segment	249m	+1.4%	+10.4%	868m	-4.2%
Materials Segment[1]	78m	+17.8%	+1.0%	282m	+18.0%

[1] Materials Segment will be de-consolidated and equity accounted for from 29 December 2020

*Period to period variances calculated using HKD

2020 Group Financial Highlights

	FY 2020		Q4 2020	
		YoY*	QoQ*	YoY*
Bookings (USD)	2,382m	+16.7%	+12.9%	+46.3%
Revenue (USD)	2,177m	+6.3%	+15.2%	+10.5%
Gross Margin **(excluding One-off Items[1])**	33.6%	-114 bps	+6 bps	-179 bps
Gross Margin	32.5%	-232 bps	-399 bps	-584 bps
EBIT (HKD)	2,007m	+71.9%	+210.3%	+256.7%
Net Profit (HKD)	1,631m	+162.0%	+330.0%	+353.4%
Net Profit Margin	9.7%	+574 bps	+1,497 bps	+1,547 bps

[1] excludes inventory provision relating to product portfolio simplification
*Period to period variances calculated using HKD

2020 Segment Results – Semiconductor Solutions

	FY2020		Q4 2020	
		YoY*	QoQ*	YoY*
Bookings (USD)	1,158m	+25.9%	+16.0%	+84.9%
Revenue (USD)	1,027m	+13.8%	+24.1%	+17.3%
Gross Margin (excl. One-off Items[1])	40.7%	-43 bps	-95 bps	-180 bps
Gross Margin	38.2%	-293 bps	-934 bps	-1019 bps
Segment Profit (HKD)	689m	+44.5%	-49.1%	-49.2%
Segment Profit Margin	8.6%	+184 bps	-548 bps	-498 bps

[1] excludes inventory provision relating to product portfolio simplification

*Period to period variances calculated using HKD

2020 Segment Results – SMT Solutions

	FY2020		Q4 2020	
		YoY*	QoQ*	YoY*
Bookings (USD)	874m	-0.7%	-9.1%	+4.7%
Revenue (USD)	868m	-4.2%	+10.4%	+1.4%
Gross Margin	31.1%	-384 bps	+119 bps	-441 bps
Segment Profit (HKD)	657m	-29.1%	+16.8%	-27.9%
Segment Profit Margin	9.8%	-343 bps	+57 bps	-421 bps

*Period to period variances calculated using HKD

2020 Segment Results – Materials

	FY2020		Q4 2020	
		YoY*	QoQ*	YoY*
Bookings (USD)	350m	+45.4%	+75.3%	+64.7%
Revenue (USD)	282m	+18.0%	+1.0%	+17.8%
Gross Margin	15.7%	+558 bps	-388 bps	+707 bps
Segment Profit (HKD)	213m	+265.0%	-33.0%	+468.1%
Segment Profit Margin	9.7%	+659 bps	-464 bps	+726 bps

Note: The Materials Business Segment will be de-consolidated and equity accounted for from 29 December 2020 onwards.

*Period to period variances calculated using HKD

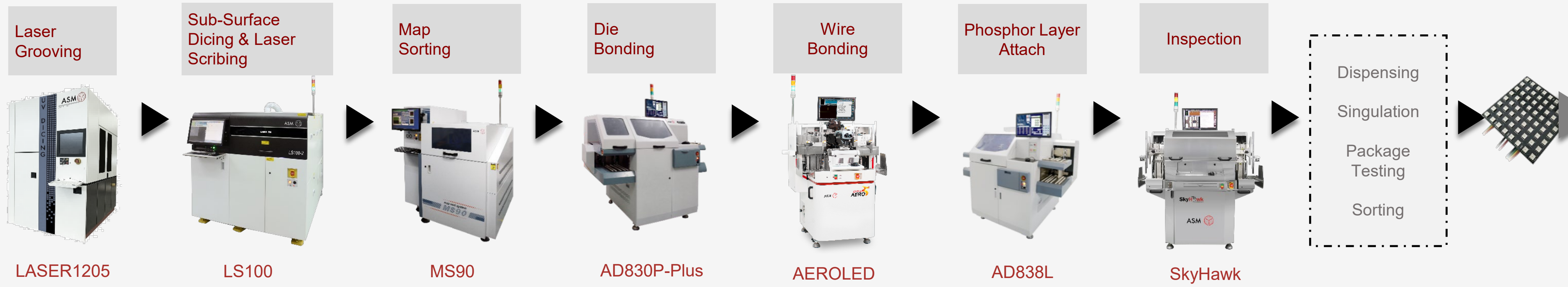
Appendix

Other Information

Core Capabilities

Comprehensive Suite of Packaging and Assembly Solutions
(A General Process Flow for LED and CIS)

Conventional LED Packaging Solutions



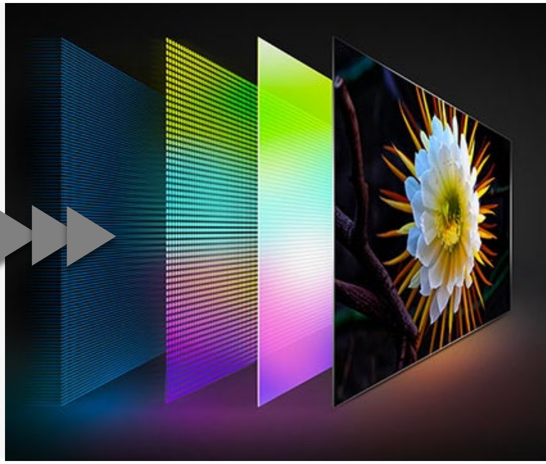
- Laser Grooving: LASER1205
- Sub-Surface Dicing & Laser Scribing: LS100
- Map Sorting: MS90
- Die Bonding: AD830P-Plus
- Wire Bonding: AEROLED
- Phosphor Layer Attach: AD838L
- Inspection: SkyHawk

Dispensing

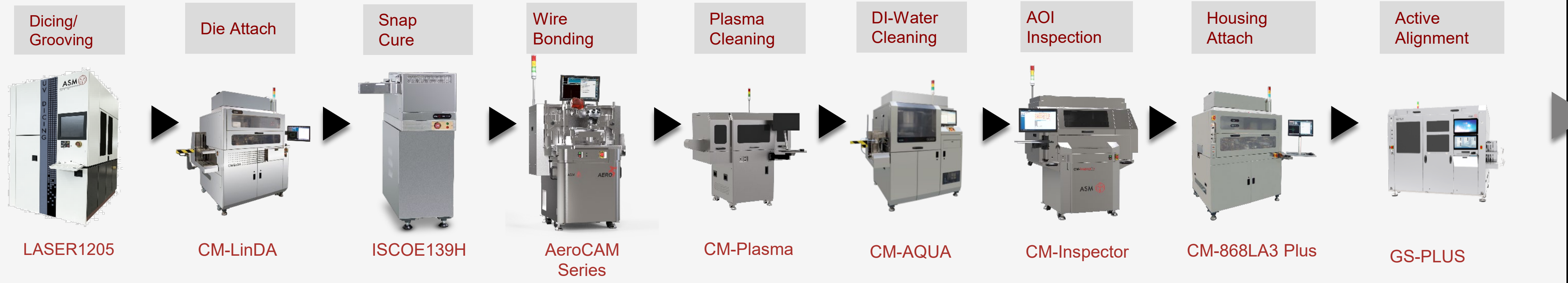
Singulation

Package Testing

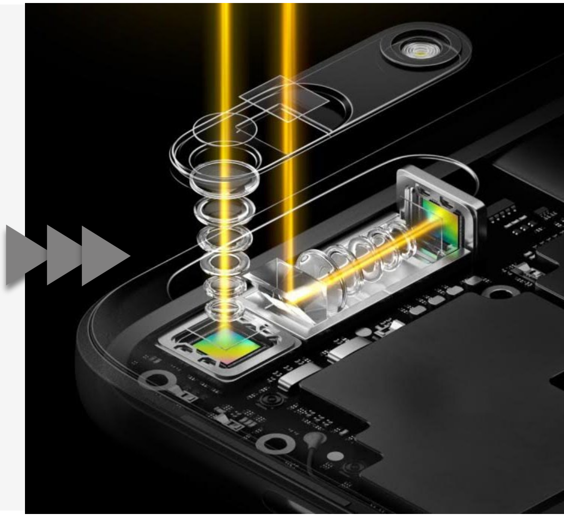
Sorting



CIS Packaging Solutions



- Dicing/ Grooving: LASER1205
- Die Attach: CM-LinDA
- Snap Cure: ISCOE139H
- Wire Bonding: AeroCAM Series
- Plasma Cleaning: CM-Plasma
- DI-Water Cleaning: CM-AQUA
- AOI Inspection: CM-Inspector
- Housing Attach: CM-868LA3 Plus
- Active Alignment: GS-PLUS

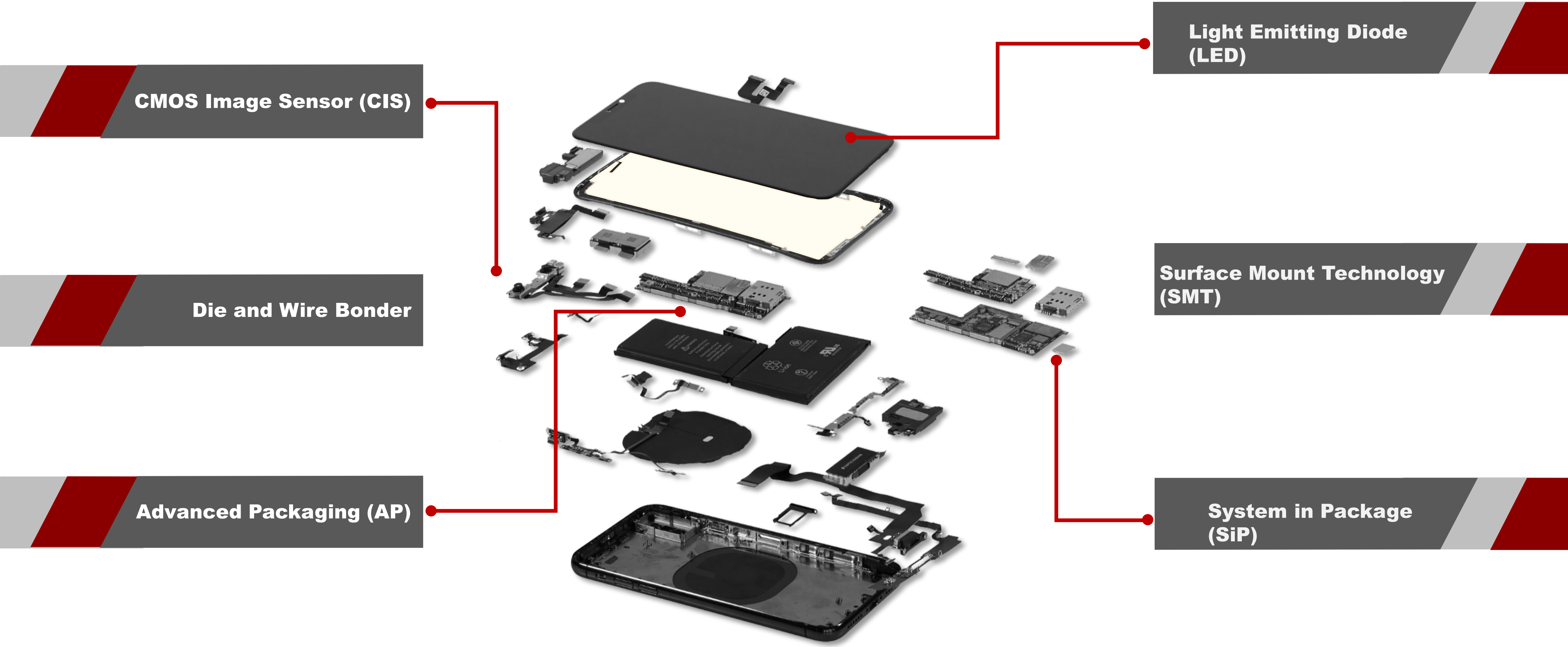


Legend

Solution offered by ASMPT

Core Capabilities

Widespread use of ASMPT Technology (Smartphone as an Example)



Light Emitting Diode (LED)

CMOS Image Sensor (CIS)

Surface Mount Technology (SMT)

Die and Wire Bonder

System in Package (SiP)

Advanced Packaging (AP)

Thank You

SINGAPORE QUALITY AWARD
2019 WINNER

2019 HKMA Quality Award
GRAND AWARD

Forbes Asia
2019
BEST OVER A BILLION

ASM Pacific Technology